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WS/SC ID# WS-10

1.9 THz Silicon Micromachined Multi-Pixel Receiver Instrument

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The 48th European Microwave Conference



The 13th European Microwave Integrated Circuits Conference



The 15th European Radar Conference

Acknowledgement

The central collage features the following elements:

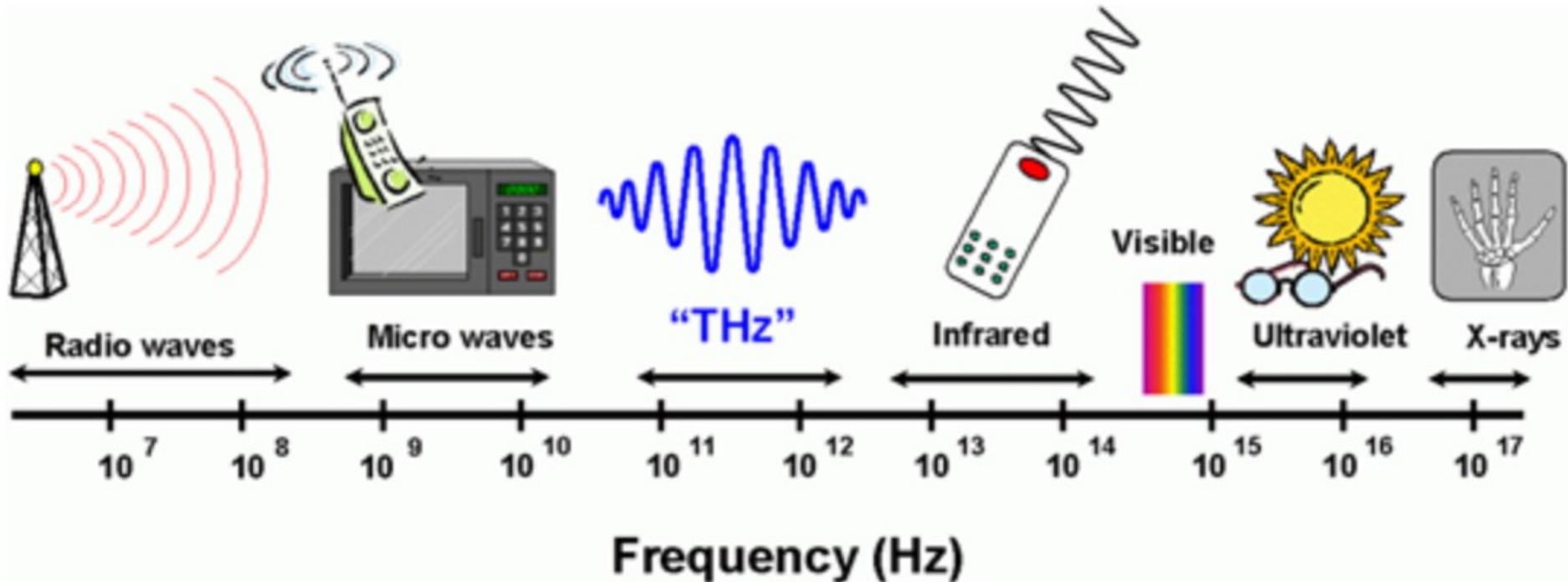
- Logos:** JPL (top left), NASA (top right).
- Applications:** Atmospheric Science, Solar System, Earth, Defense, Health (middle left).
- Platforms:** High Altitude Balloon, Airborne Platform (DC/SOFA), Earth Orbits/Sounders, Planetary/Small Body Sounders (middle top).
- Project Title:** SUBMILLIMETER-WAVE ADVANCED TECHNOLOGY 2017-2018 (center).
- Visuals:** A large red and blue wave graphic labeled 'SWATM', a rocket launch, a green flower, a human torso scan, and various technical diagrams and component photos.

Individual team members are listed in the following order:

- Row 1: Maria Alonso, Goutam Chattopadhyay, Ken Cooper, Robert Dengler, Andy Fung, John Gill, Hamid Javadi, Cecile Jung, Boris Karasik.
- Row 2: Adrian Tang, Anders Skalare, Seth Sin, Daniel Cunnane, Jose Siles, Theodore Reck, Jenna Kloosterman, Erich Schlecht, Lorene Samoska, David G. Ovejero, Alex Peralta, Imran Mehdi.
- Row 3: Jon Kawamura, Choonsup Lee, Robert Lin.

This work was carried out at the California Institute of Technology, Jet Propulsion Laboratory, under contract with the National Aeronautics and Space Administration.

Terahertz (Submillimeter) Waves

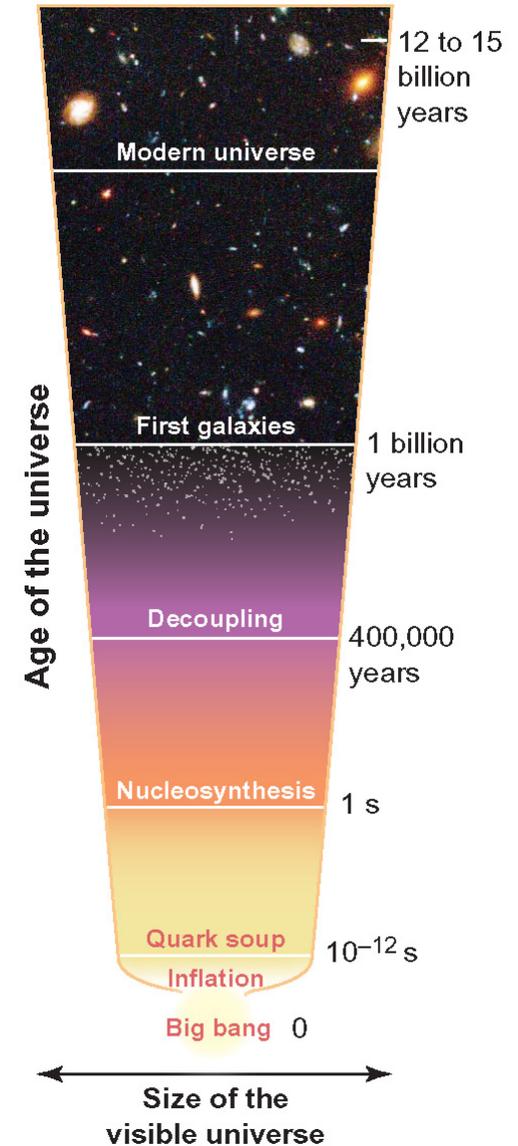
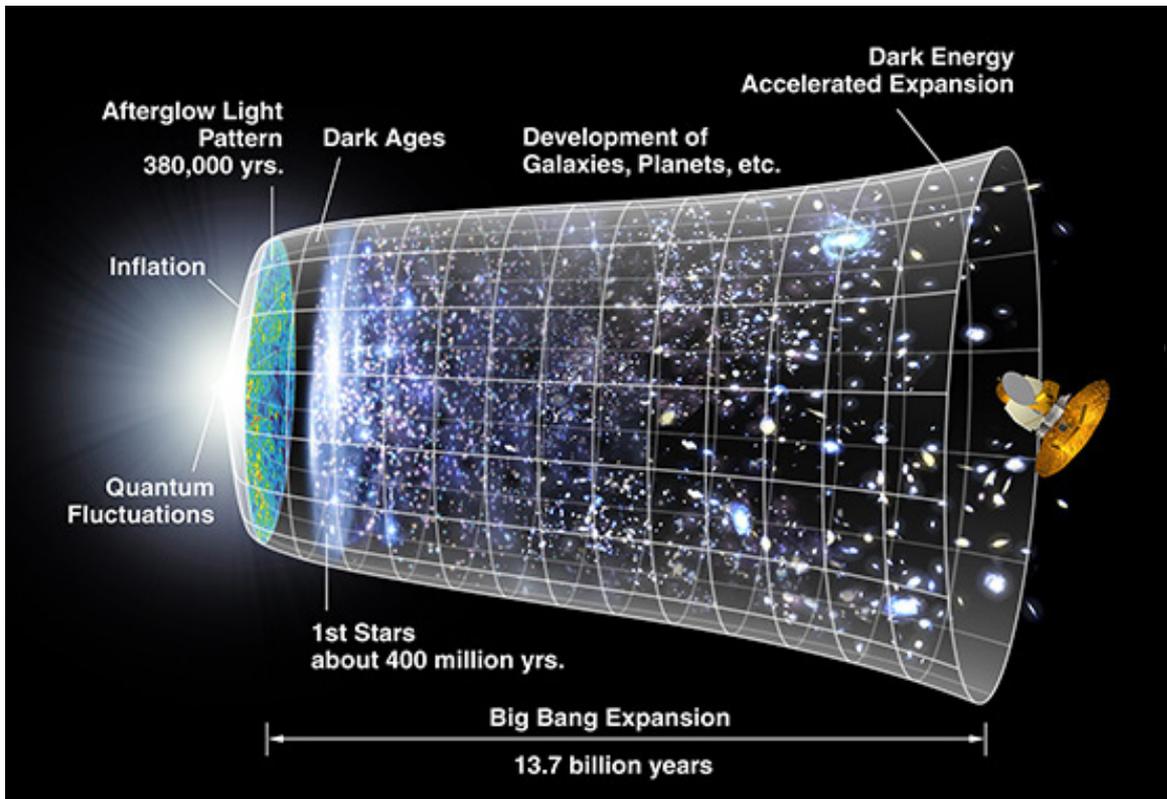


Loosely defined: $1 \text{ mm} > \lambda > 100 \text{ } \mu\text{m}$

$300 \text{ GHz} < \nu < 3 \text{ THz}$

Most of the radiation in the Universe is emitted at submillimeter-wavelengths, peaking at 3 THz (excluding CMB radiation).

Terahertz Science: Big Bang

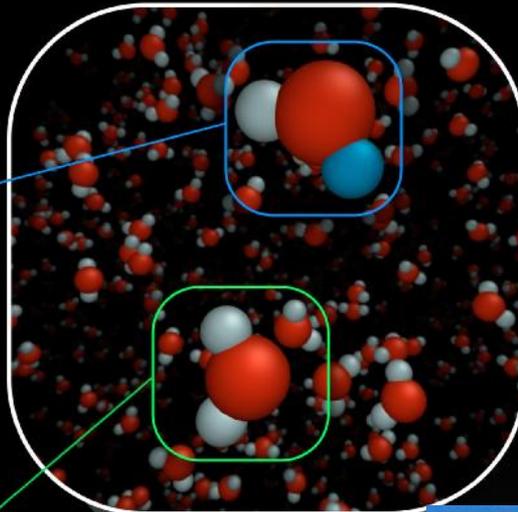
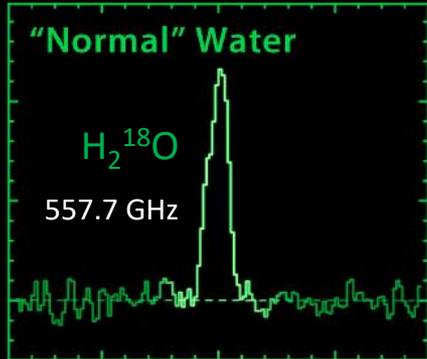


History of our Universe: Started with a Big Bang, and here we are, after 13.8 billion years!

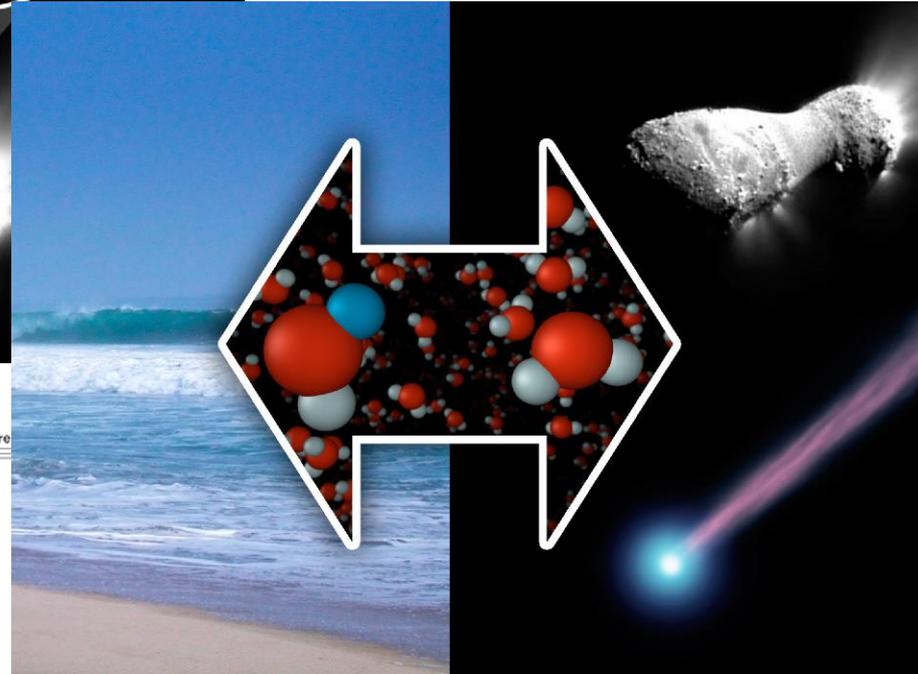
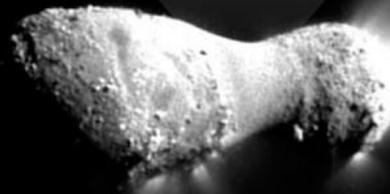
Terahertz Science: Water

“Earth’s water may have come from comets!”

Herschel Space Observatory’s HIFI Instrument (JPL).



$H_2^{17}O$ (552 GHz) and $H_2^{16}O$ (556.9 GHz)



LETTER

Nature, October 2011

doi:10.1038/nature

Ocean-like water in the Jupiter-family comet 103P/Hartley 2

Paul Hartogh¹, Dariusz C. Lis², Dominique Bockelée-Morvan³, Miguel de Val-Borro¹, Nicolas Biver³, Michael Küppers⁴, Martin Emprechtinger², Edwin A. Bergin⁵, Jacques Crovisier³, Miriam Rengel¹, Raphael Moreno³, Slawomira Szutowicz⁶ & Geoffrey A. Blake²

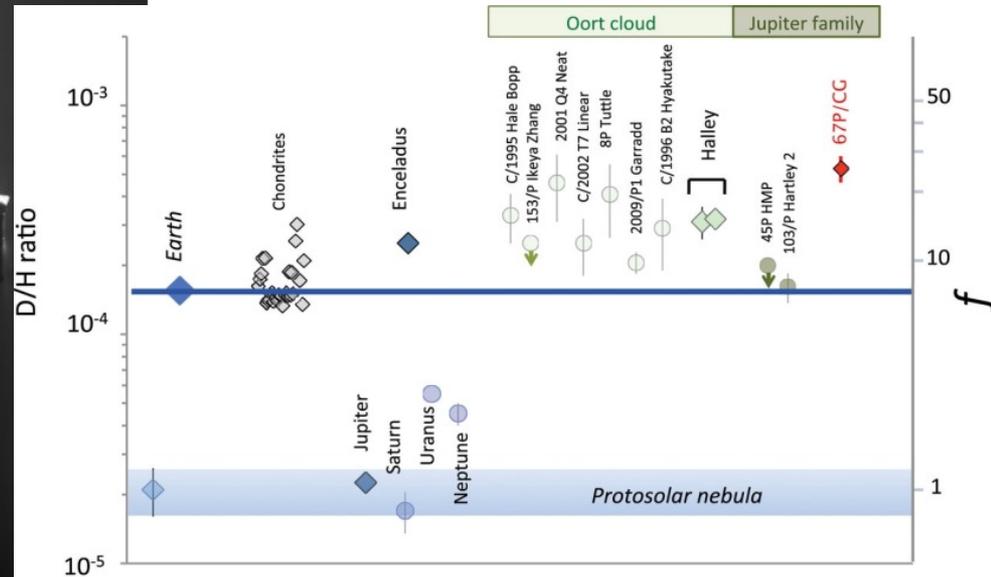
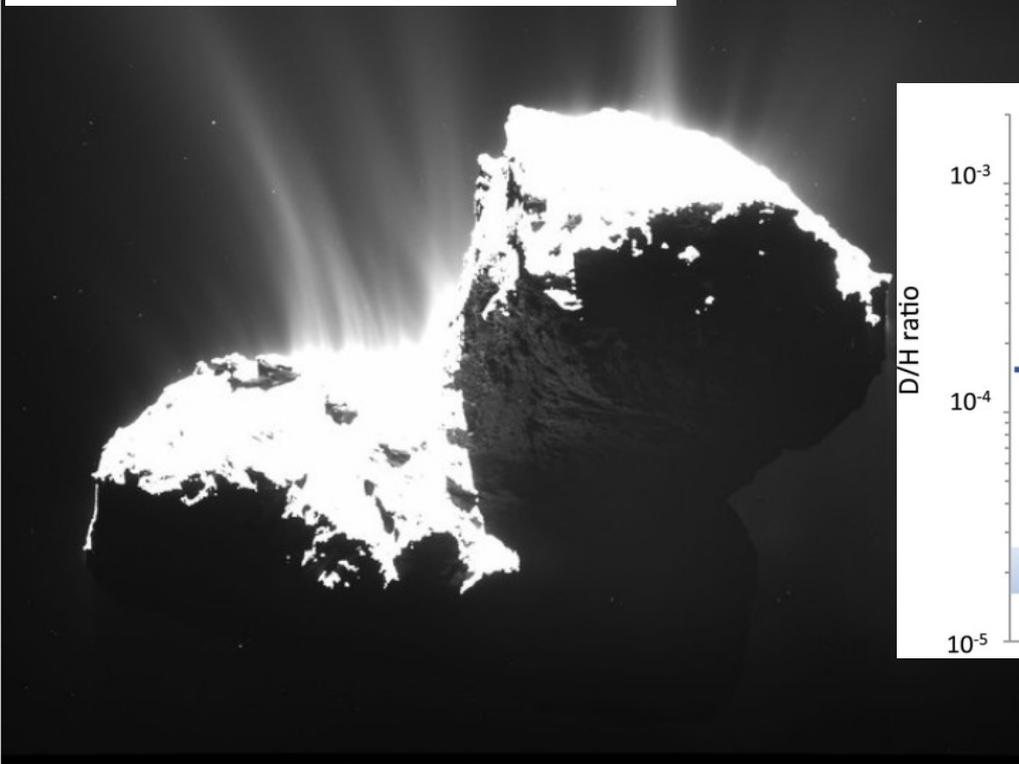
Terahertz Science: ROSETTA

Science, Jan. 23, 2015

MIRO Instrument on ROSETTA Orbiter

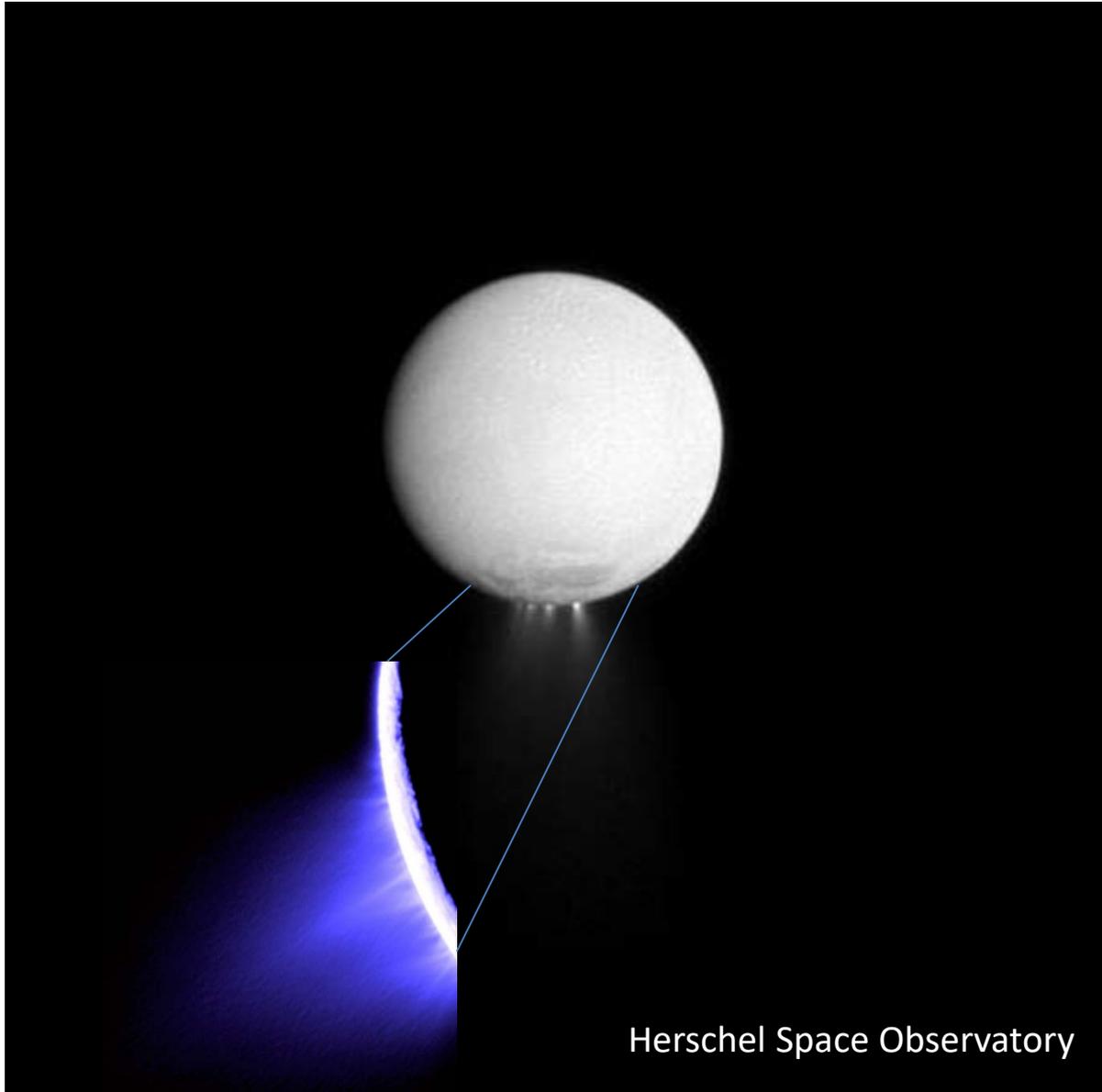
Subsurface properties and early activity of comet 67P/Churyumov-Gerasimenko

Samuel Gulkis,^{1†} Mark Allen,¹ Paul von Allmen,¹ Gerard Beaudin,² Nicolas Biver,³ Dominique Bockelée-Morvan,³ Mathieu Choukroun,¹ Jacques Crovisier,³ Björn J. R. Davidsson,⁴ Pierre Encrenaz,^{2*} Therese Encrenaz,^{3*} Margaret Frerking,¹ Paul Hartogh,⁵ Mark Hofstadter,¹ Wing-Huen Ip,⁶ Michael Janssen,¹ Christopher Jarchow,⁵ Stephen Keihm,¹ Seungwon Lee,¹ Emmanuel Lellouch,³ Cedric Leyrat,³ Ladislav Rezac,⁵ F. Peter Schloerb,^{7,†} Thomas Spilker^{1†}



November 2014 image of 67P comet showing faint gas and dust.

Terahertz Science: Enceladus



**Saturn's moon
Enceladus rains
down water on
Saturn!**

**Now we know where
the water vapor in
Saturn's upper
atmosphere come from!**

**Enceladus is the only
moon in the Solar
System known to
influence the chemical
composition of its
parent planet.**

Herschel Space Observatory

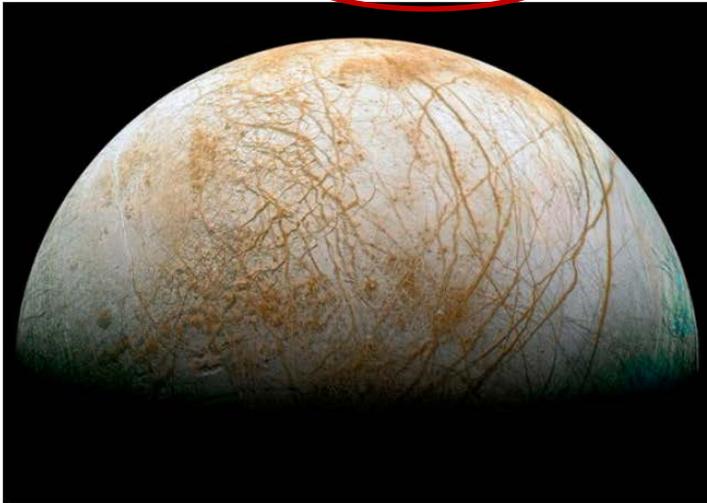
Terahertz Science: Europa



Jupiter's Icy Moon Europa: Best Bet for Alien Life?

By Nola Taylor Redd, Space.com Contributor August 22, 2014 06:00am ET

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Under a thick crust of ice, Europa might have an ocean warmed by tidal interactions with Jupiter. This tidal flexing could also produce a geologically active core that might in turn create hydrothermal vents on the ocean floor. [Pin it](#)

Credit: NASA/JPL/Ted Stryk

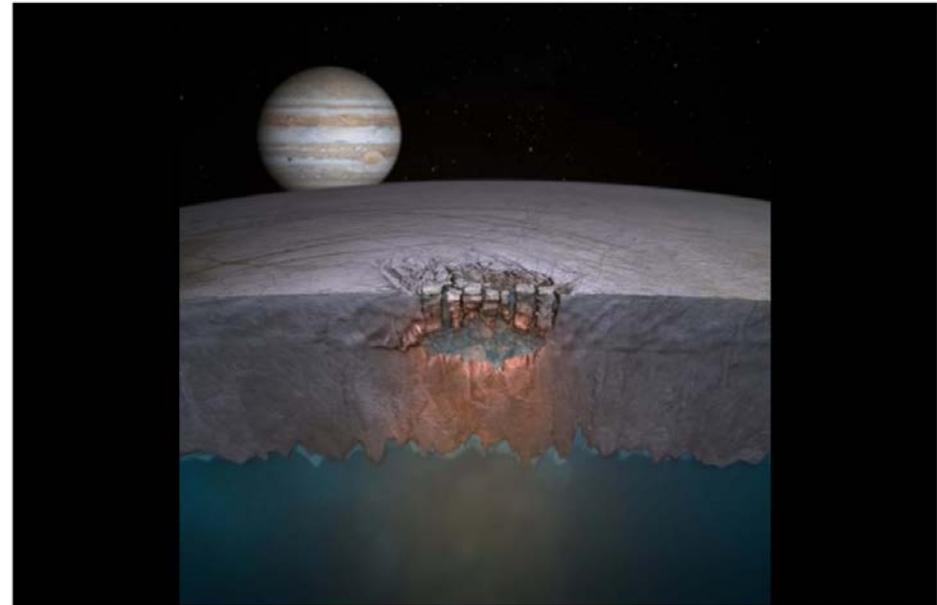
[View full size image](#)

WASHINGTON — Jupiter's moon Europa doesn't look like a particularly inviting place for life to thrive; the icy satellite is nearly 500 million miles (800 million kilometers) from the sun, on average.

But beneath its icy crust lies a liquid ocean with more water than Earth contains. This ocean is shielded from harmful radiation, making Europa one of the solar system's best bets to host alien life.

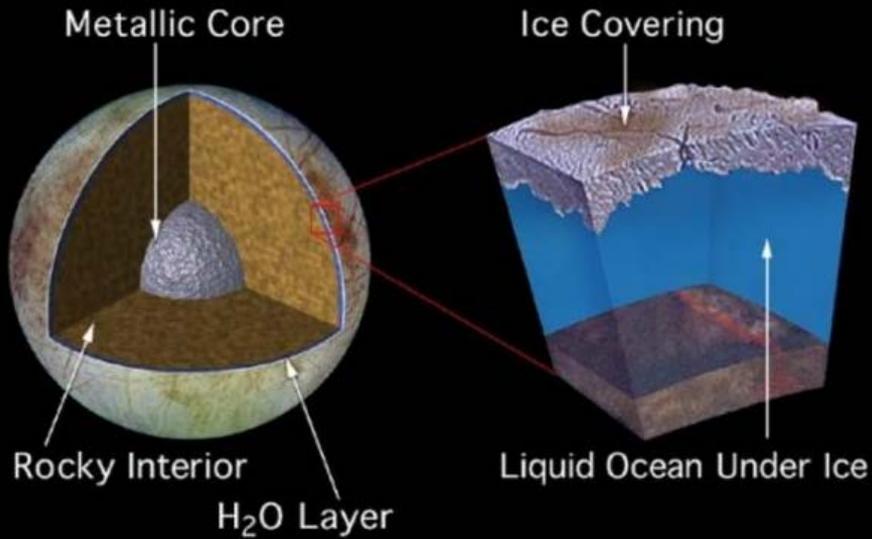
“Europa has the best chance of having life there today,” said Britney Schmidt, who studies the moon at the University of Texas at Austin and led the new study appearing in the journal Nature.

Jupiter's moon Europa: Lake theory boosts hopes for life



November 16, 2011, Washington Post. Paper in Nature.

Terahertz Science: Europa



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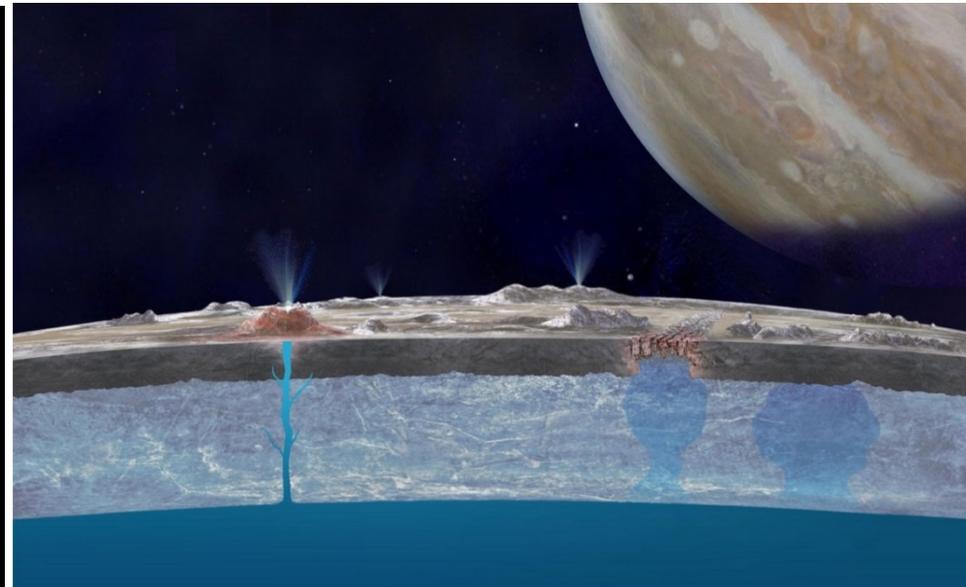
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Water plumes spark a race to Jupiter moon Europa

31 December 2013 by [Lisa Grossman](#)

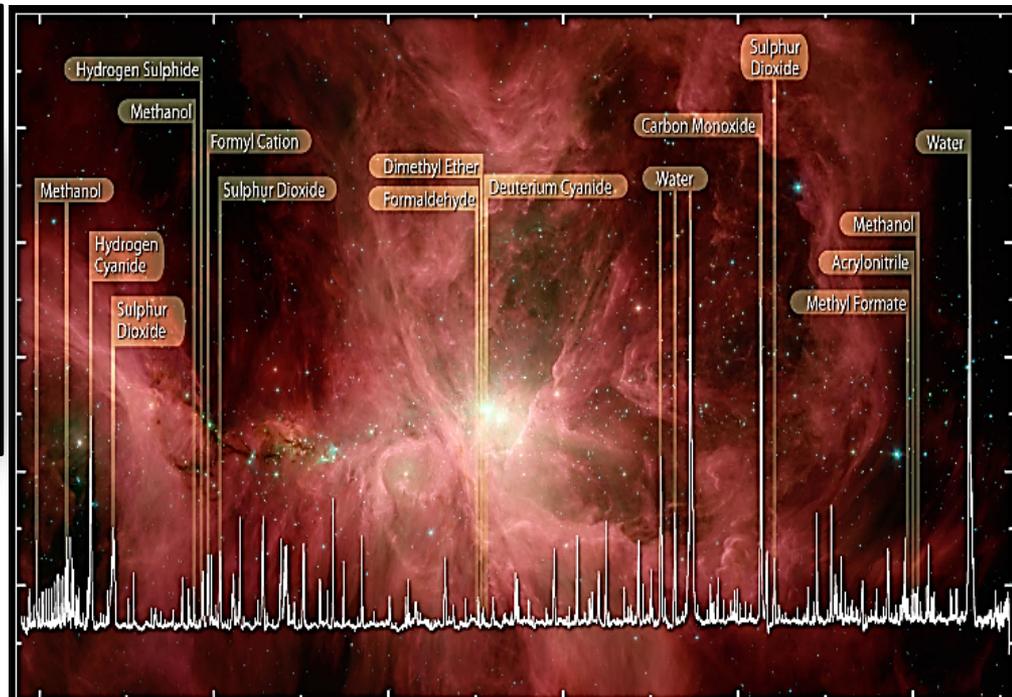
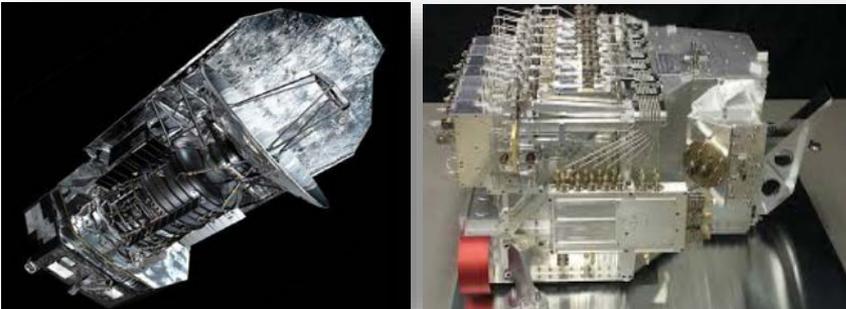
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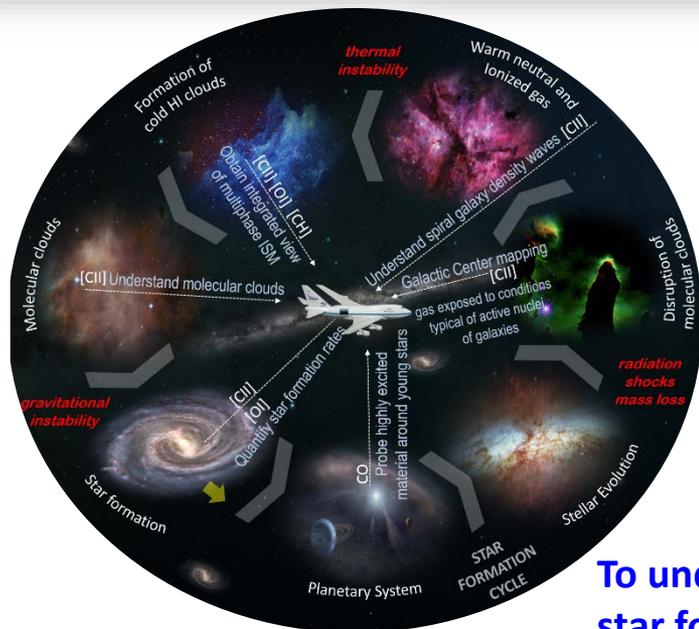
(NASA/ESA/K. Retherford/SWRI) - This is an artist's concept of a plume of water vapor ejected off the icy surface of Europa. Spectroscopic measurements from NASA's Hubble Space Telescope led scientists to calculate that the plume rises to an altitude of 125 miles and probably rains frost back onto the surface.

Terahertz Science: Astrophysics



HIFI Spectrum of Water and Organics in the Orion Nebula

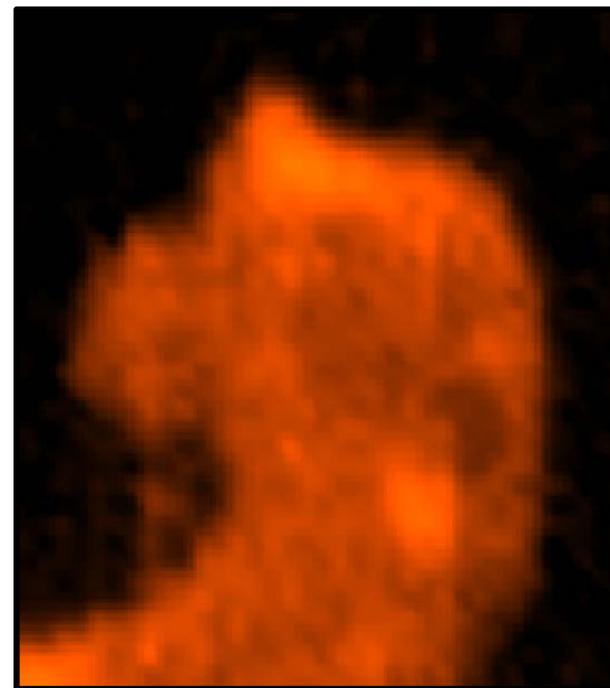
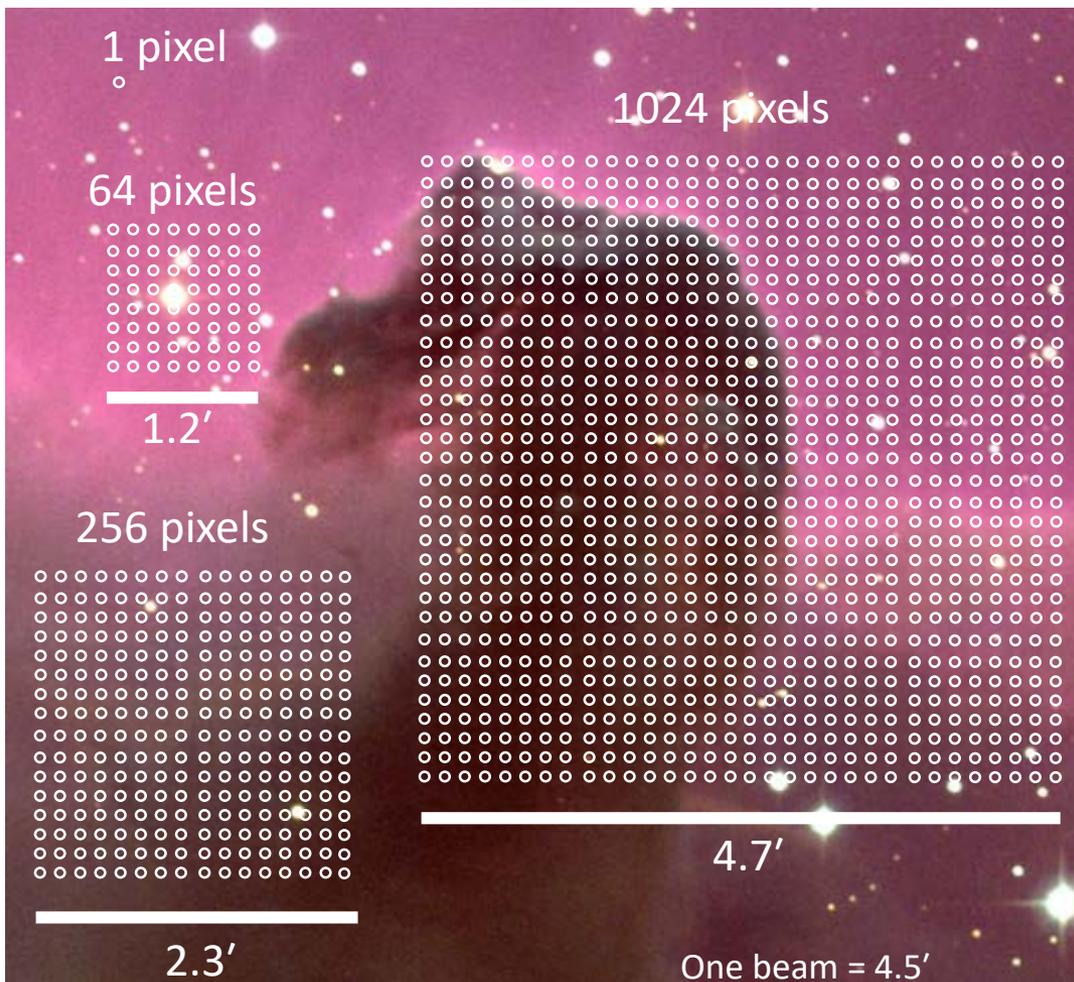
© ESA, HEXOS and the HIFI consortium
E. Bergin



To understand the star formation cycle

Frequency coverage: 480 GHz – 1910 GHz
(7 channels, dual pol.)

Mapping Capability

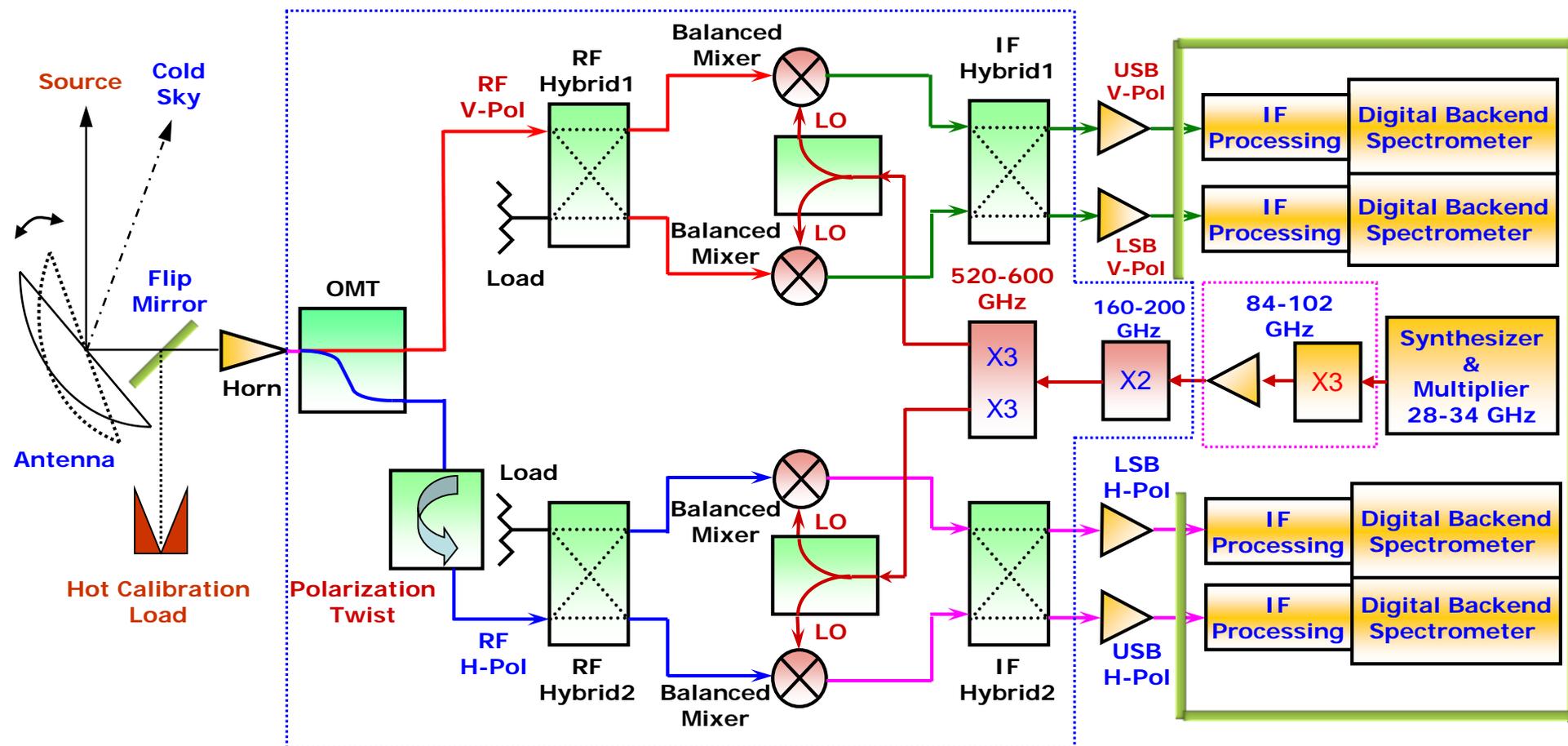


“Submillimeter light” of the CO molecule

Beam spacing in the sky: $\sim 2f/\# \times \lambda$

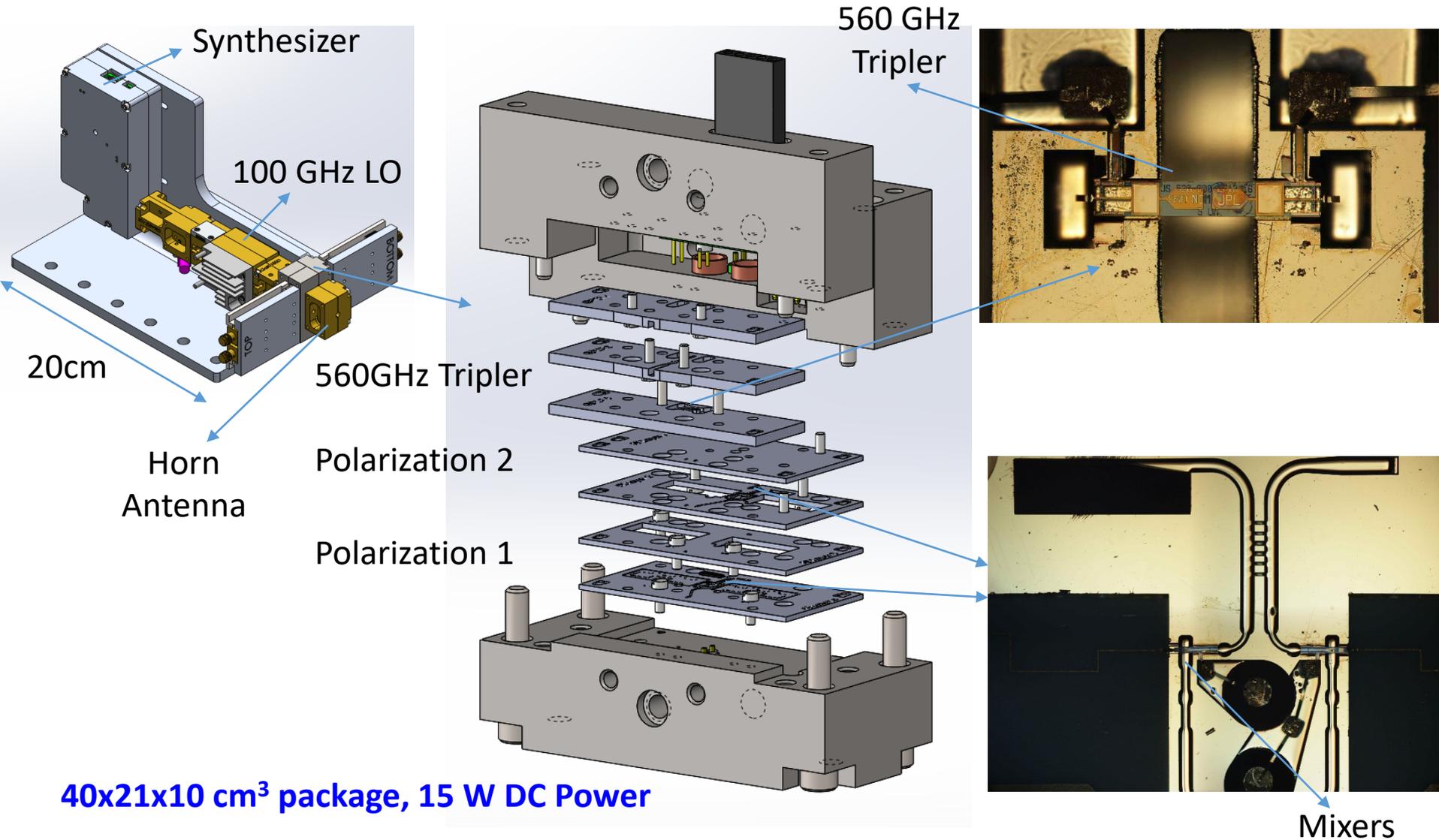
Ref: Chris Walker, University of Arizona

Complex and Compact Instruments



Ref: G. Chattopadhyay, T. Reck, A. Tang, C. Jung-Kubiak, C. Lee, J. Siles, E. Schlecht, Y. M. Kim, M-C F. Chang, and I. Mehdi, "Compact Terahertz Instruments for Planetary Missions," *Proc. 9th European Conference on Antennas and Propagation (EuCAP)*, Lisbon, Portugal, April 2015.

Packaging of Terahertz Instruments



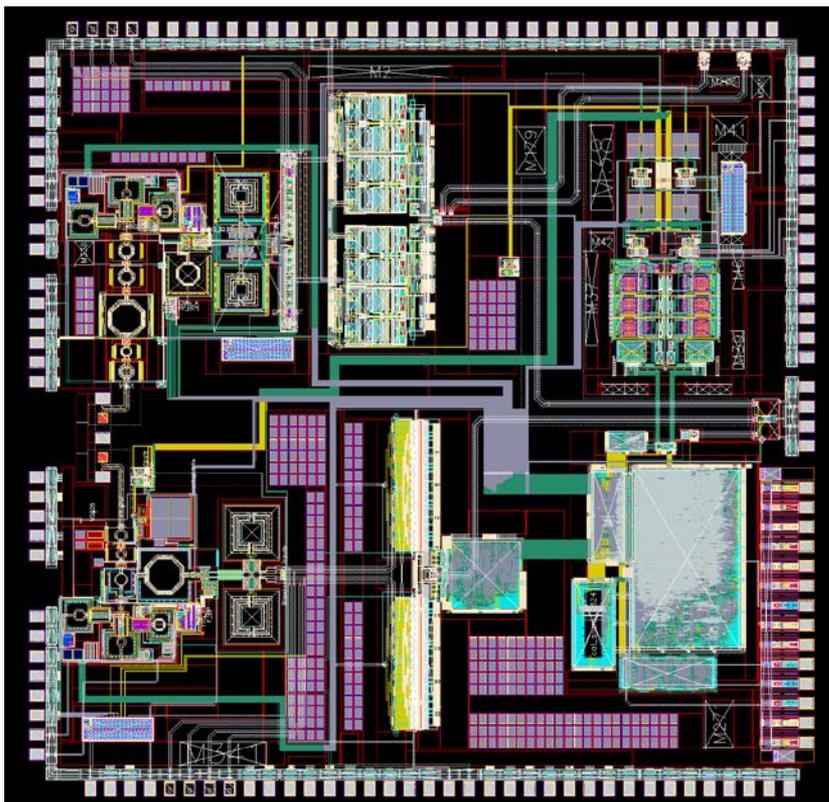
Ref: G. Chattopadhyay, T. Reck, C. Lee, and C. Jung-Kubiak, "Micromachined Packaging for Terahertz Systems," *Proceedings of the IEEE*, vol. 105, no. 6, pp. 1139-1150, June 2017.

Leveraging Smart Phone Technology



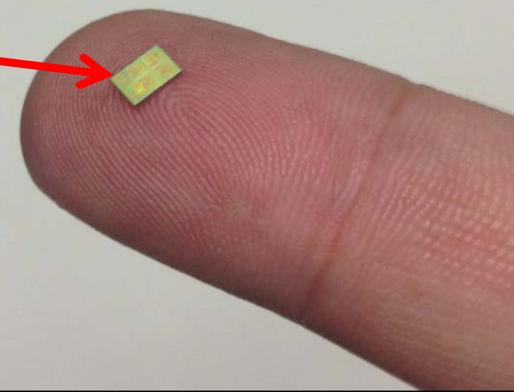
Leveraging Smart Phone Technology

Imagine what this could do for the size & weight of instrument electronics!



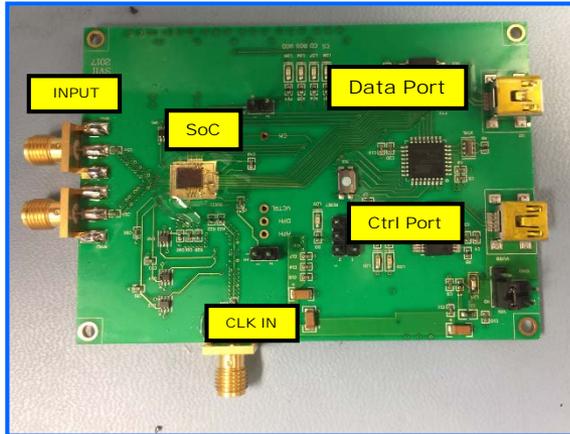
IEEE 802.15.3c Chipset

- ❑ 280,000 circuits
- ❑ 600,000 lines of code

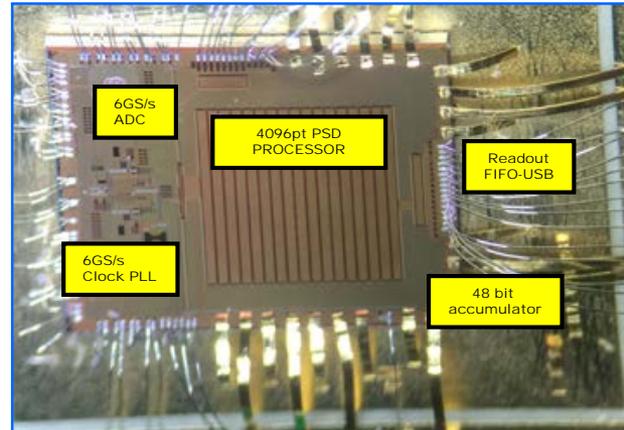


3 GHz Bandwidth SoC Backend Spectrometer

Spectrometer SVII Module



System-on-Chip



Electrical Parameters

| Parameter | Minimum | Typical | Maximum | Unit |
|------------------------------------|---------|----------------------------|---------|------|
| Clock Frequency (Han enabled) | 1 | - | 6000 | MHz |
| Clock Frequency (Han disabled) | 1 | 6000 | 6000 | MHz |
| Aliasable Bandwidth | - | - | 9000 | MHz |
| Interleaving Factor | - | 2 | - | X |
| Physical Number of Bits | - | 3 | - | bit |
| Signal to Quantization Noise Ratio | 14.2 | 16.8 | 19 | dB |
| Number of FFT Channels | - | 4096 | - | # |
| Windowing Type | - | Selectable Han or Rectange | - | - |
| Input Format | - | Differential | - | - |

Ref: A. Tang, T. Reck, and G. Chattopadhyay, "CMOS System-on-Chip Techniques in Millimeter-Wave/THz Instruments and Communications for Planetary Explorations," *IEEE Communications Magazine*, vol. 54, no. 10, pp. 176-182, October 2016.

Silicon Micromachined Based Packaging

Silicon Micromachining

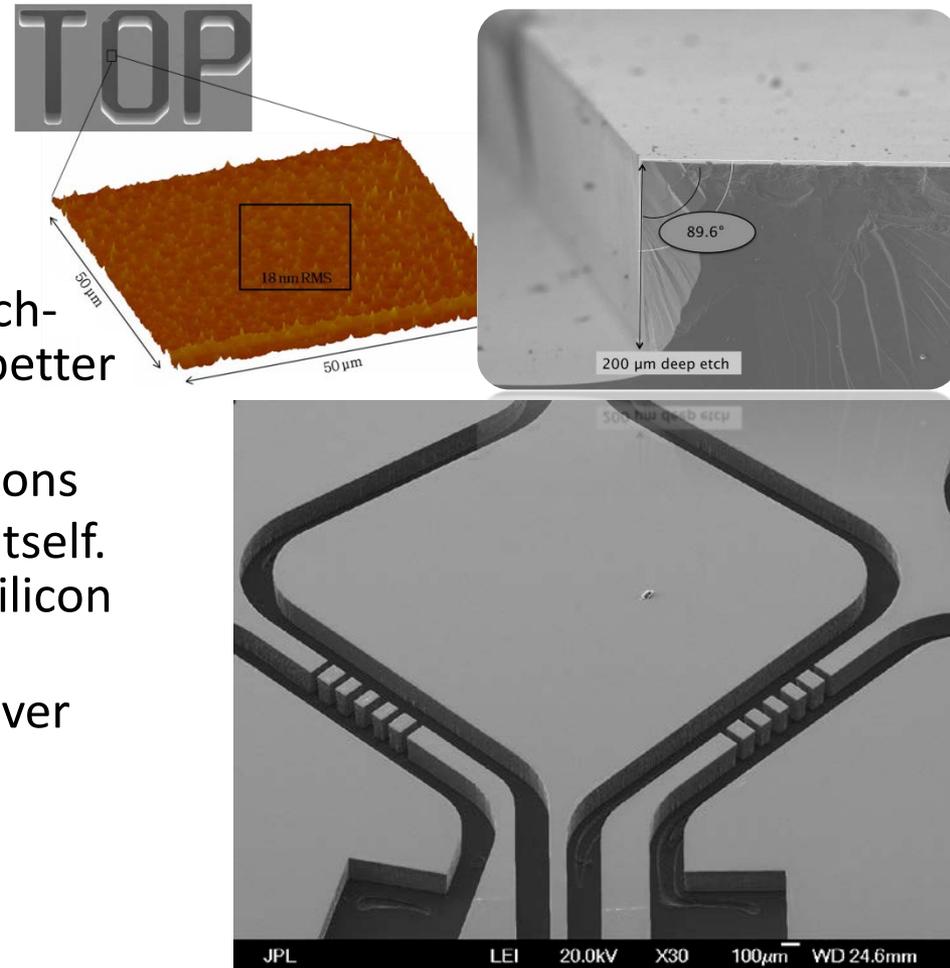
- Etch silicon wafer with plasma using a photolithographic pattern

Advantages:

- Potential for lower cost because of batch-processed device fabrication, yielding better uniformity too.
- Lithographically precise feature definitions
- Integration of bias & IF lines on silicon itself. Future potential for integrated CMOS silicon devices.
- Potential for higher density 2D transceiver arrays.

Disadvantages:

- **Challenge of wafer alignment.**

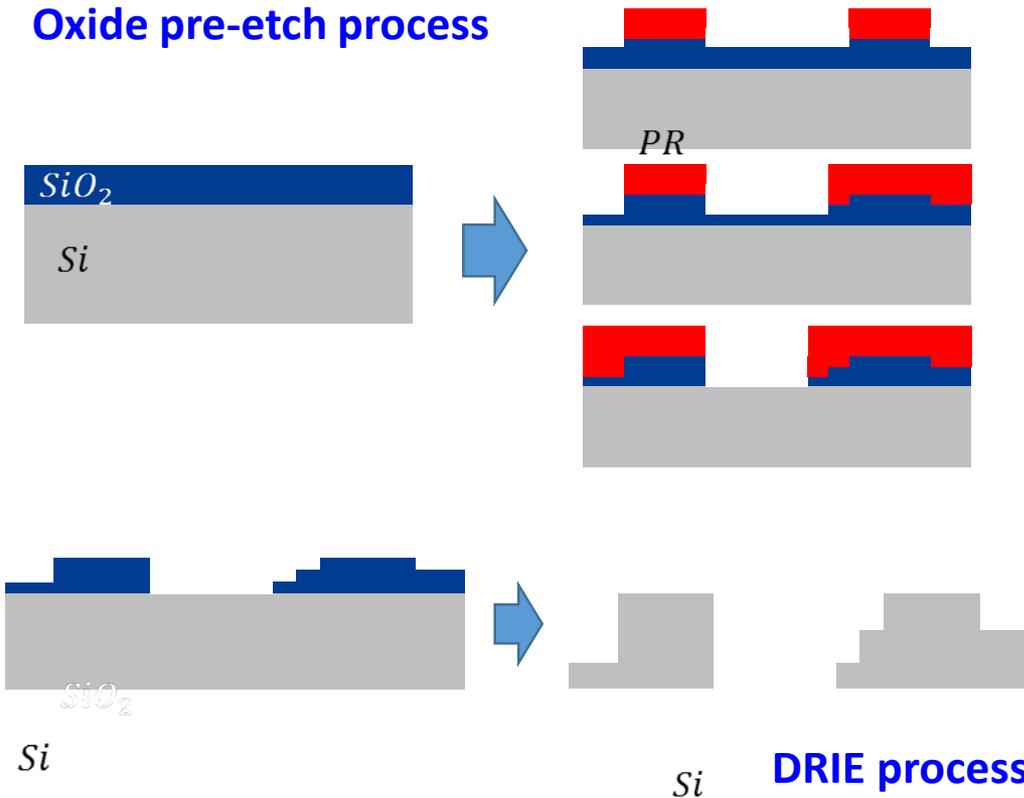


Ref: C. Jung-Kubiak, T. Reck, J. V. Siles, R. Lin, C. Lee, J. Gill, K. Cooper, I. Mehdi, and G. Chattopadhyay, "A Multi-Step DRIE Process for Complex Terahertz Waveguide Components," *IEEE Transactions on Terahertz Science and Technology*, vol. 6, no. 5, pp. 690-695, September 2016.

Deep Reactive Ion Etching (DRIE)

- Use of an optimized Bosch process to etch silicon: alternate exposures of SF_6 and C_4F_8 plasmas. Optimization of power, gas ratios, and timing for each step.
- Use SiO_2 as hard mask (selectivity of 150:1) to etch Silicon

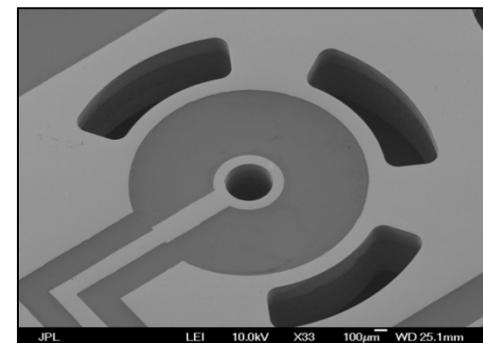
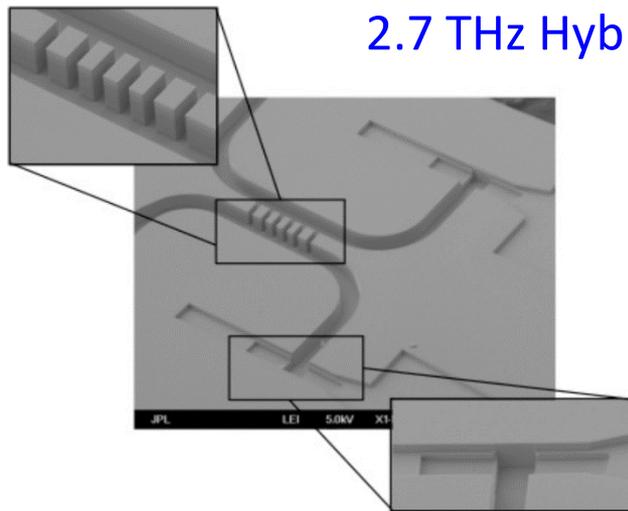
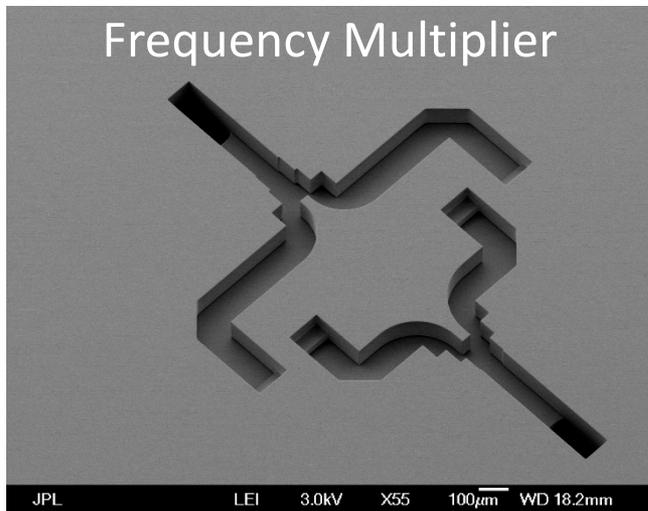
Oxide pre-etch process



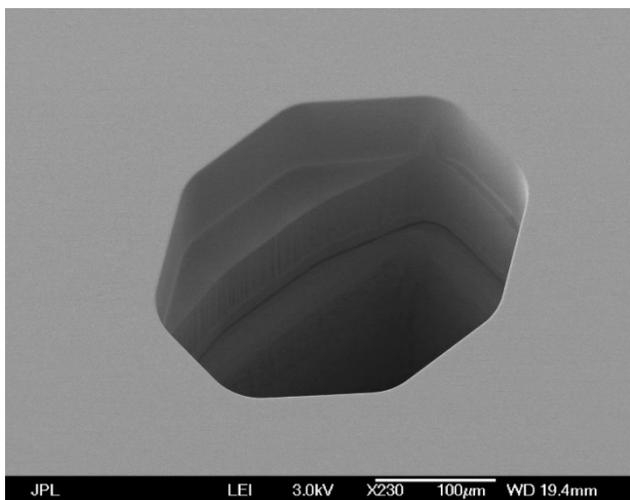
- Use of photoresist to do SiO_2 patterning.
- Etching of differential patterns to ensure precise control of the final target.
- Etching using Inductive Coupled Plasma (ICP) process (etch rate of ~ 70 nm/min).
- DRIE process to etch the silicon, with oxide as the only mask. **NO photoresist.**

Ref: C. Jung-Kubiak, T. Reck, J. V. Siles, R. Lin, C. Lee, J. Gill, K. Cooper, I. Mehdi, and G. Chattopadhyay, "A Multi-Step DRIE Process for Complex Terahertz Waveguide Components," *IEEE Transactions on Terahertz Science and Technology*, vol. 6, no. 5, pp. 690-695, September 2016.

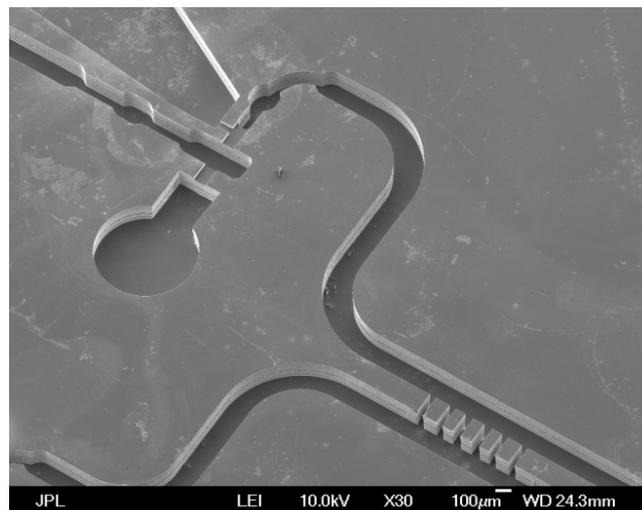
Silicon Micromachined Components



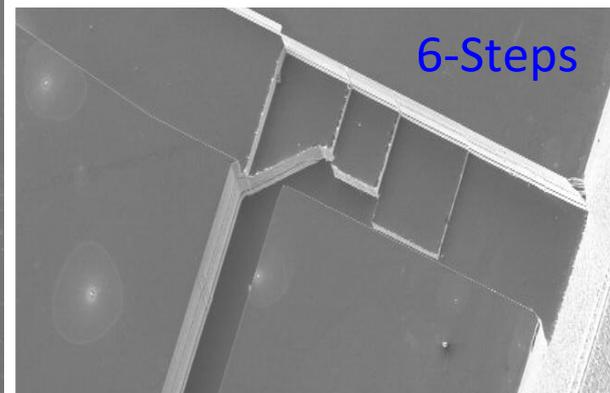
Co-axial IF output



Transition



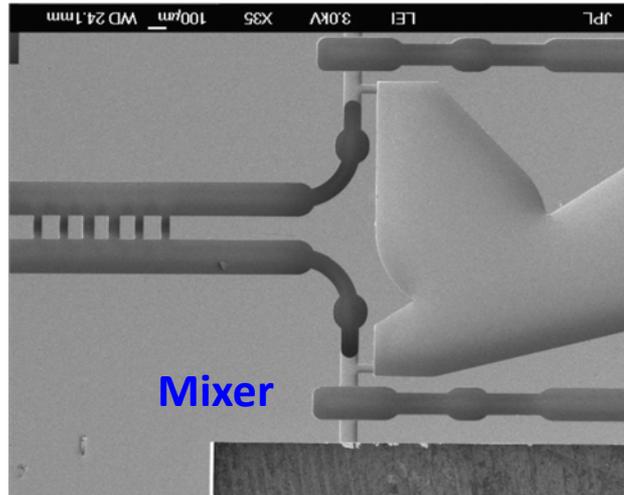
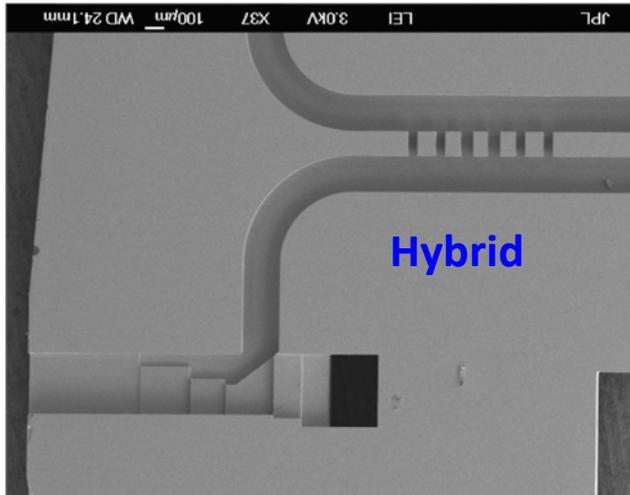
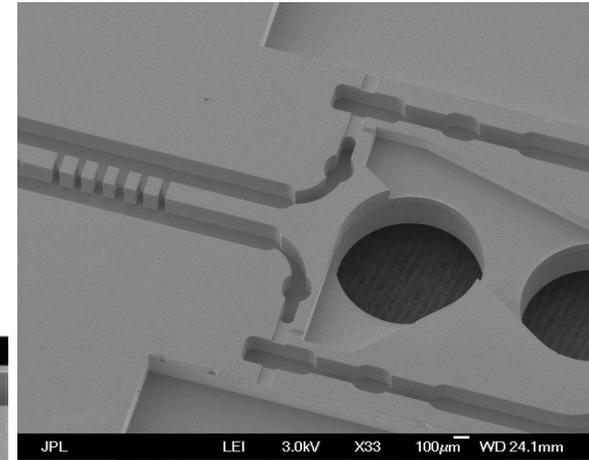
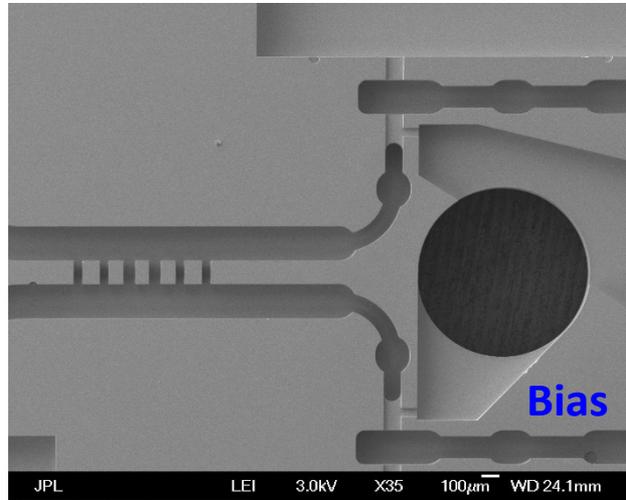
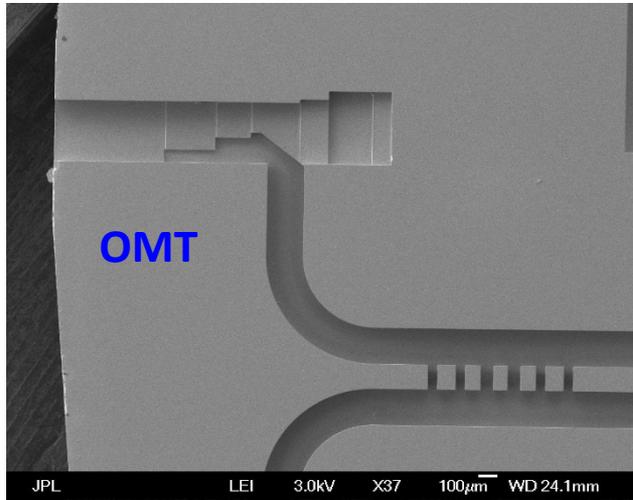
Complete Receiver



Ortho-Mode Transducer

Ref: G. Chattopadhyay, T. Reck, C. Lee, and C. Jung-Kubiak, "Micromachined Packaging for Terahertz Systems," *Proceedings of the IEEE*, vol. 105, no. 6, pp. 1139-1150, June 2017.

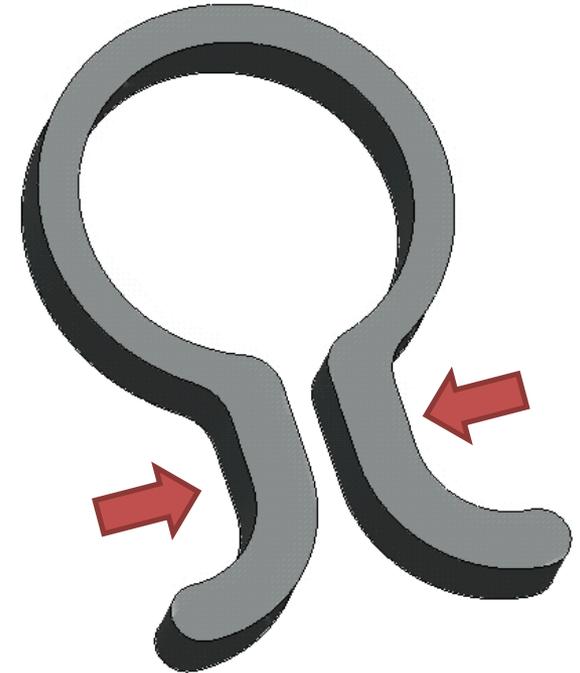
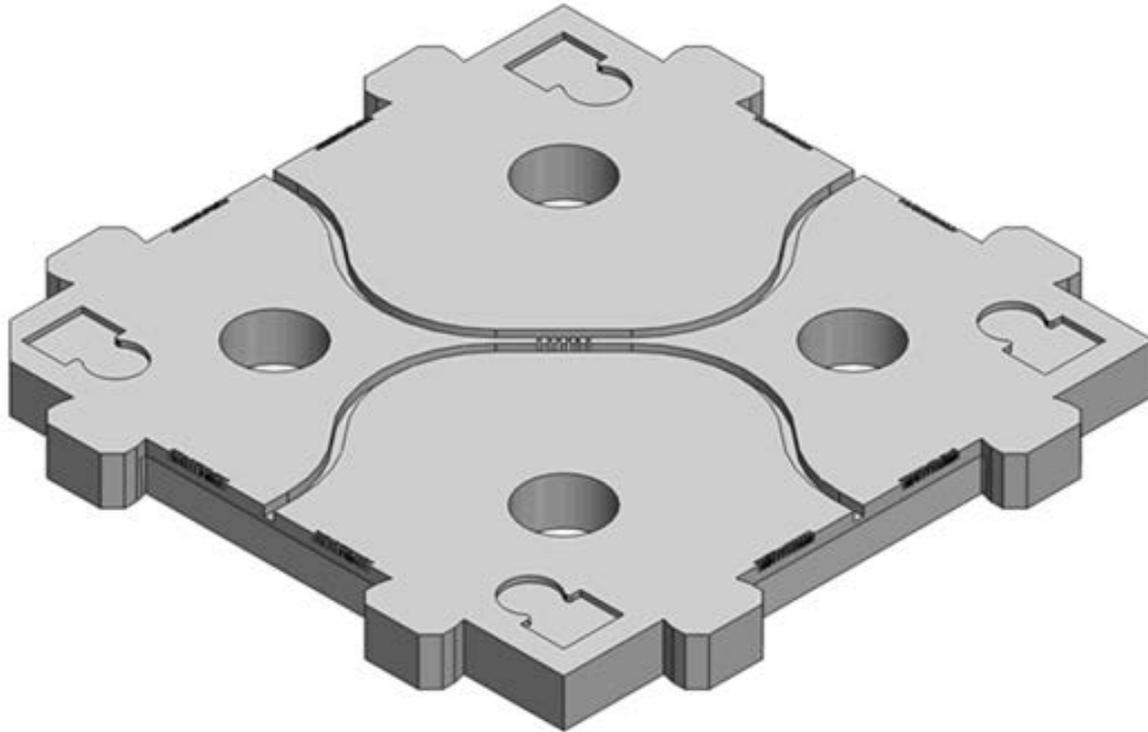
Silicon Micromachined Front-End



Different silicon micromachined layers before gold deposition.

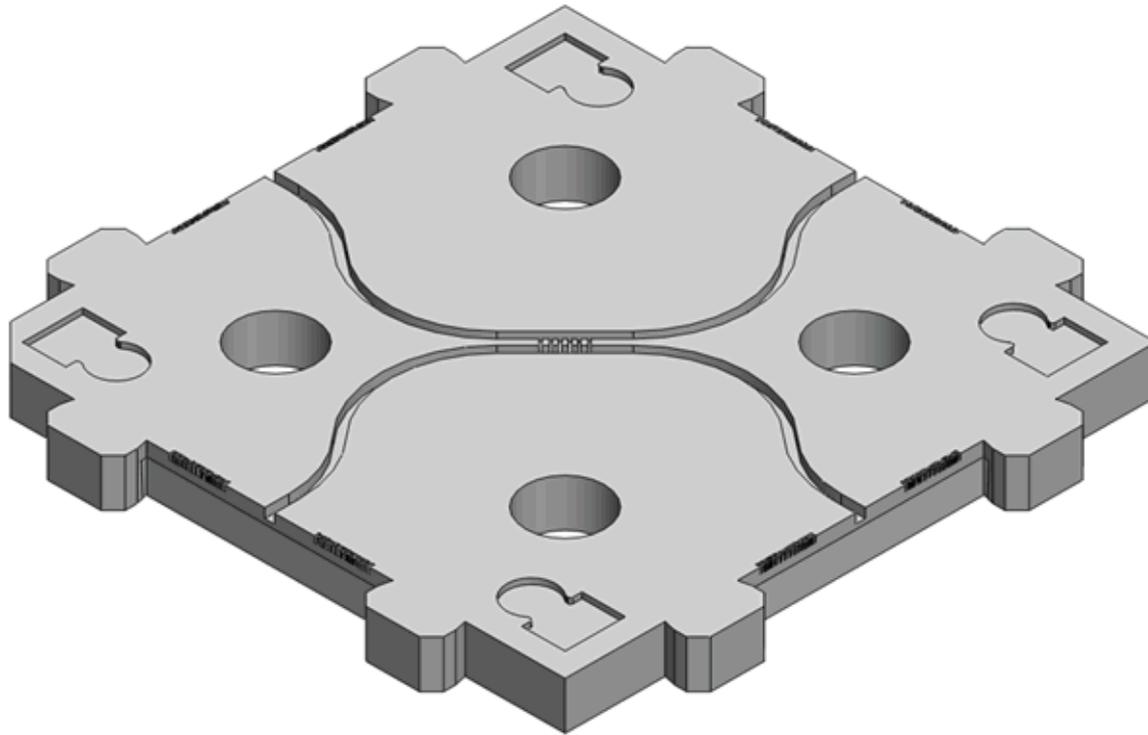
Ref: G. Chattopadhyay, T. Reck, C. Lee, and C. Jung-Kubiak, "Micromachined Packaging for Terahertz Systems," *Proceedings of the IEEE*, vol. 105, no. 6, pp. 1139-1150, June 2017.

Wafer Alignment



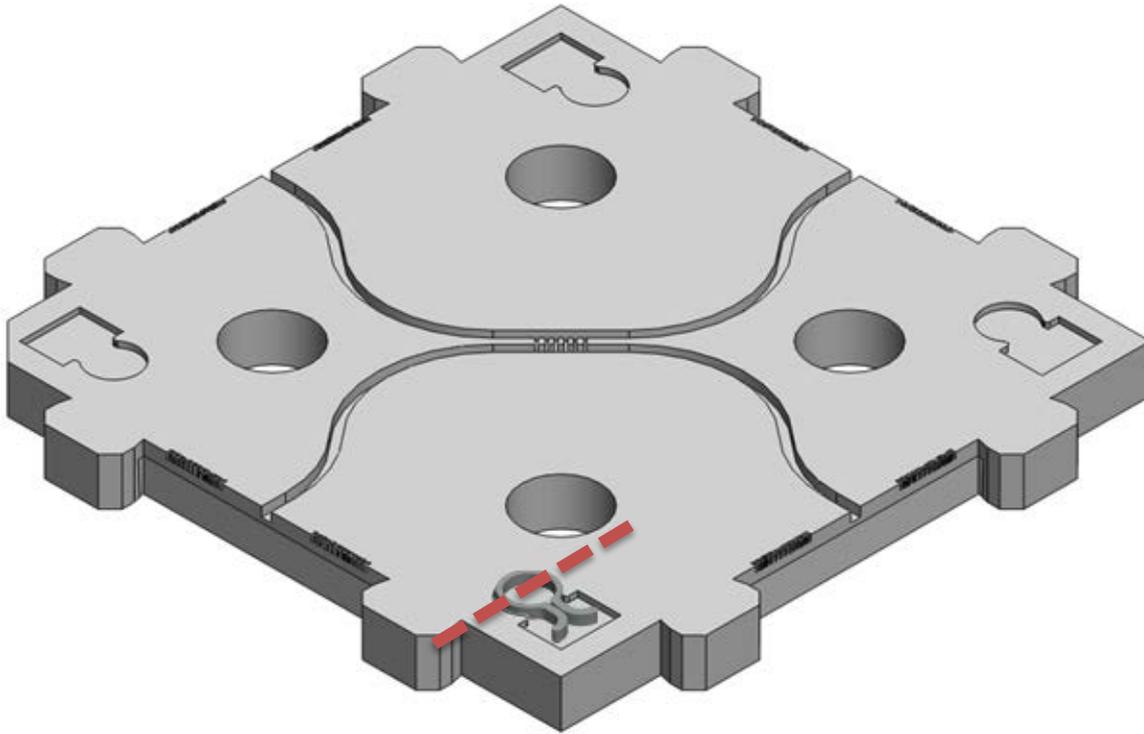
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Wafer Alignment



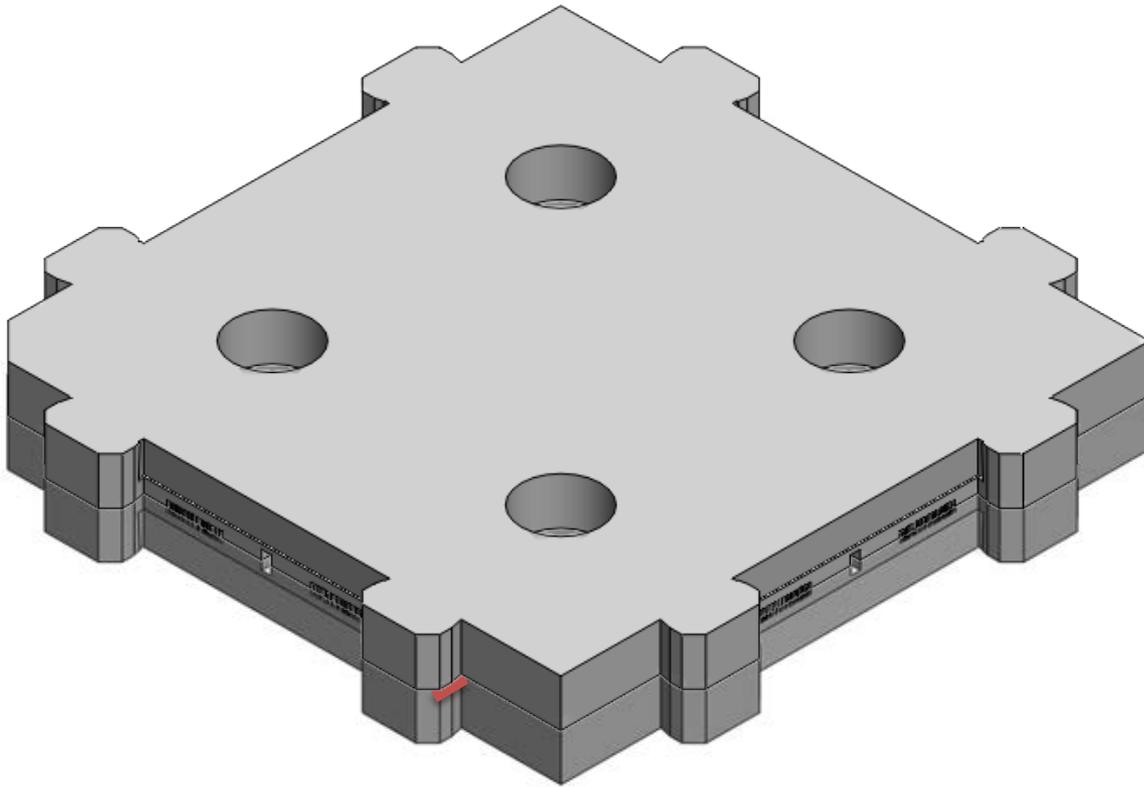
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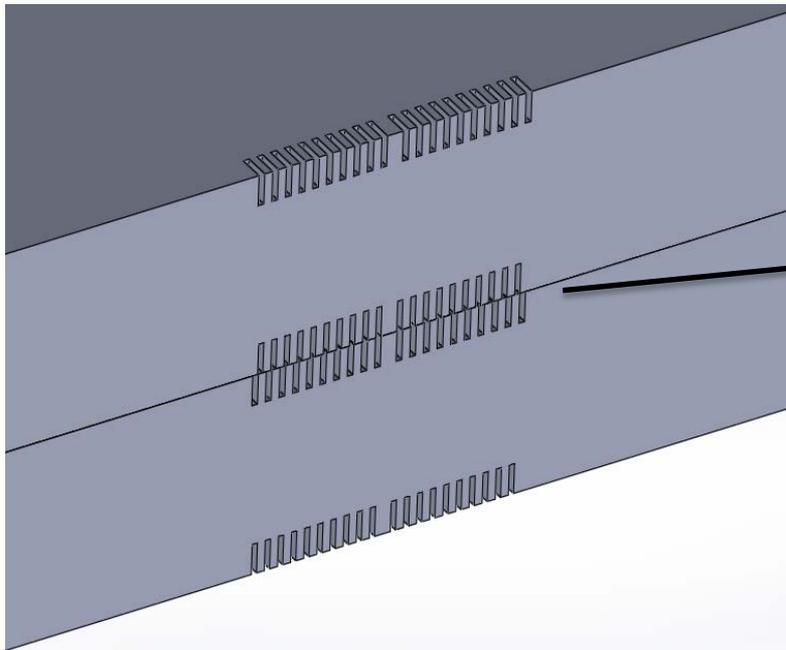
Wafer Alignment



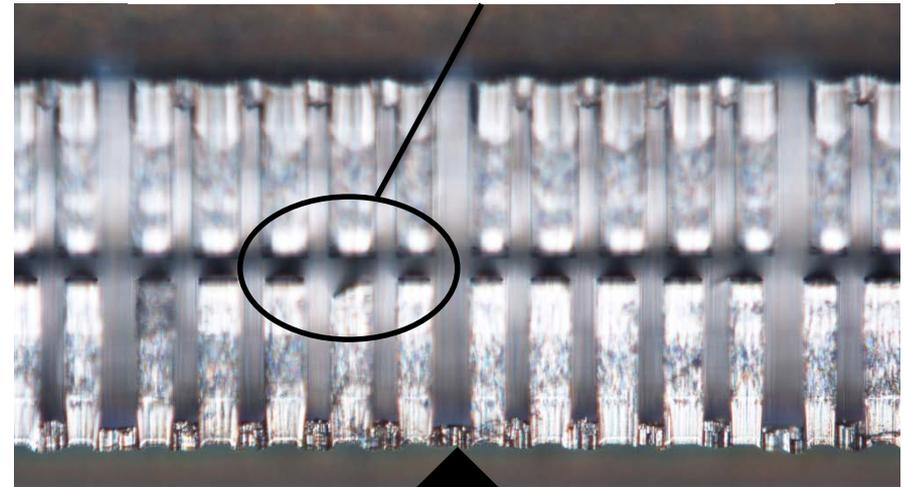
Ref: G. Chattopadhyay, T. Reck, C. Lee, and C. Jung-Kubiak, "Micromachined Packaging for Terahertz Systems," *Proceedings of the IEEE*, vol. 105, no. 6, pp. 1139-1150, June 2017.

Wafer Alignment

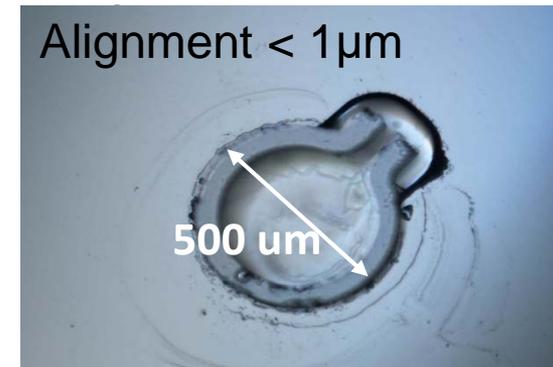
- How do we align individual silicon wafers?



Axis misalignment $1\mu\text{m} \pm 1\mu\text{m}$



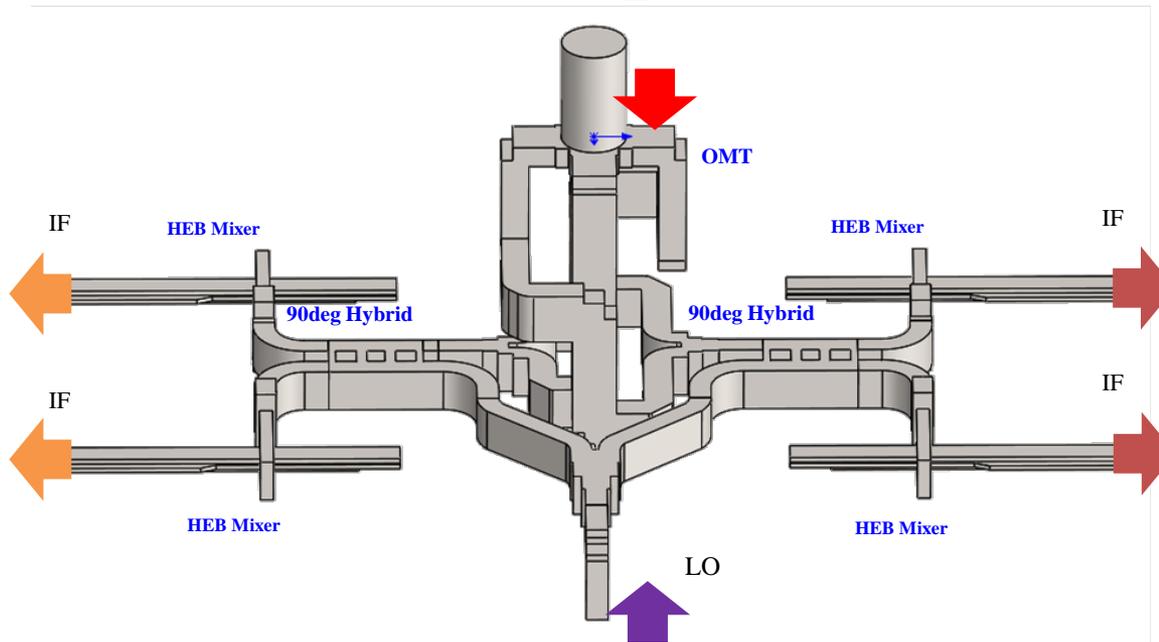
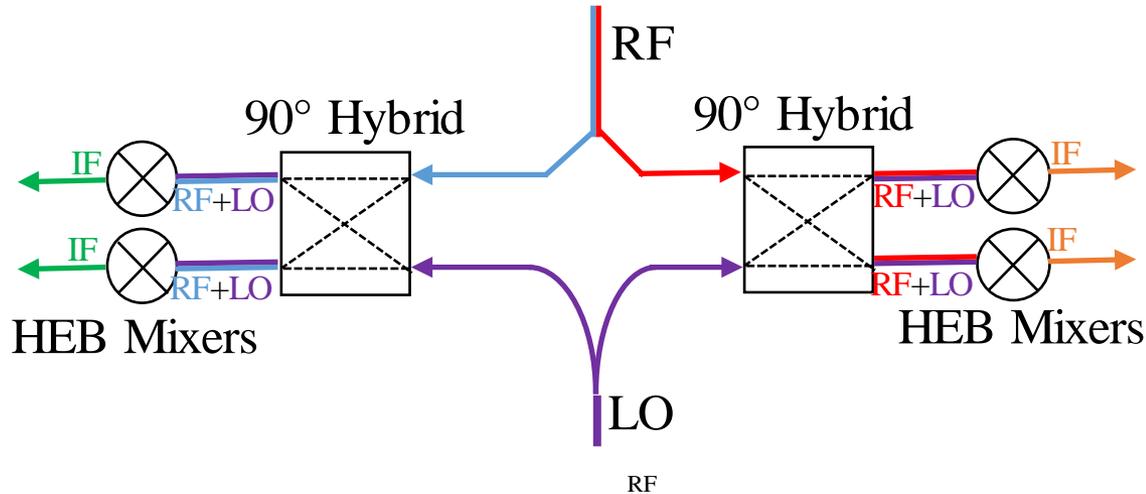
Alignment $< 1\mu\text{m}$



- Enables characterization of alignment schemes
- Improves hand alignment

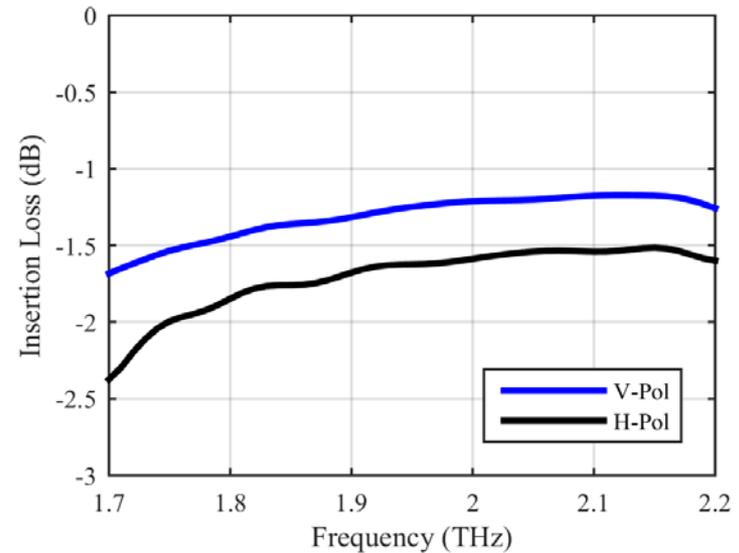
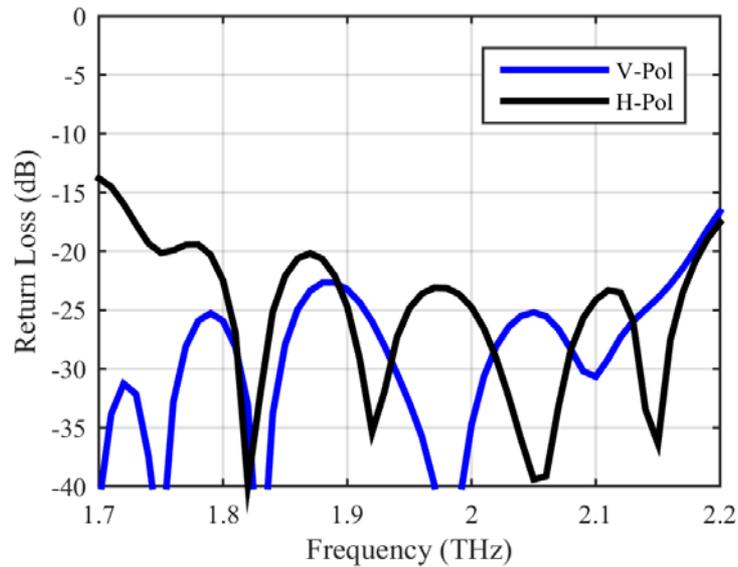
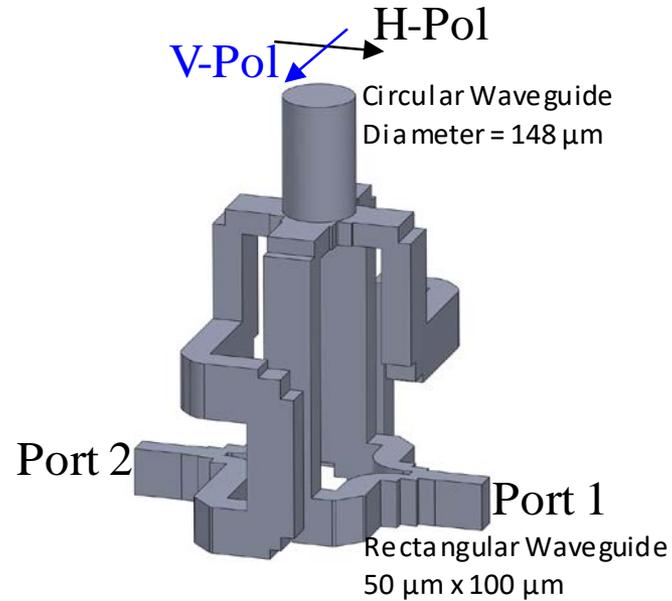
Ref: G. Chattopadhyay, T. Reck, C. Lee, and C. Jung-Kubiak, "Micromachined Packaging for Terahertz Systems," *Proceedings of the IEEE*, vol. 105, no. 6, pp. 1139-1150, June 2017.

Receiver Architecture for 1.9 THz Array

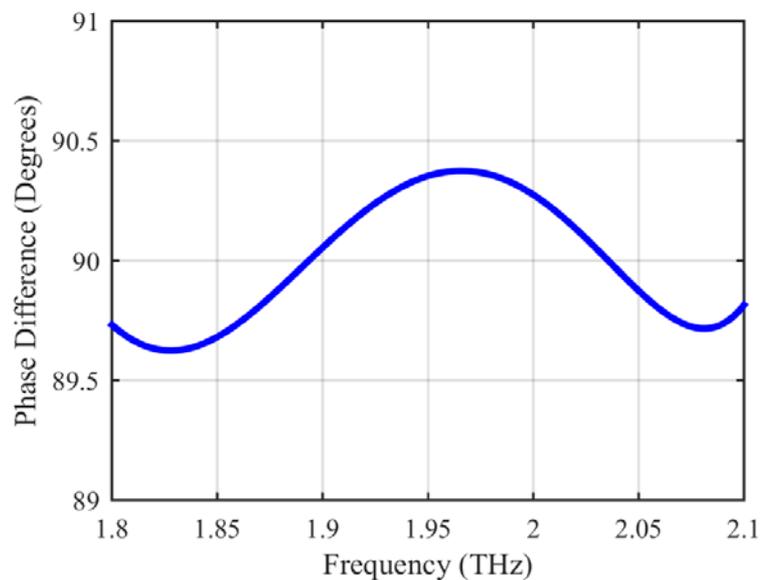
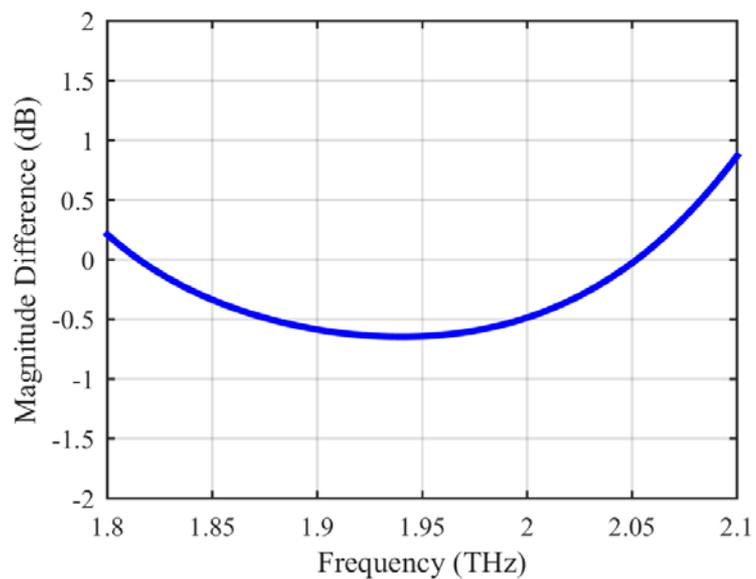
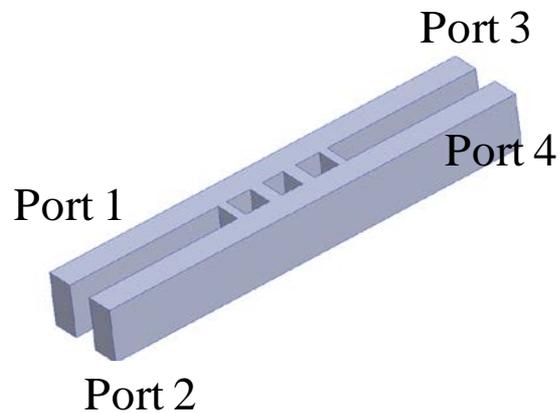


Ref: M. Alonso-delPino, T. Reck, C. Lee, C. Jung-Kubiak, N. Llombart, I. Mehdi, and G. Chattopadhyay, "Micro-Lens Antenna Integrated in a Silicon Micromachined Receiver at 1.9 THz," *Proc. 10th European Conference on Antennas and Propagation (EuCAP)*, Davos, Switzerland, April 2016.

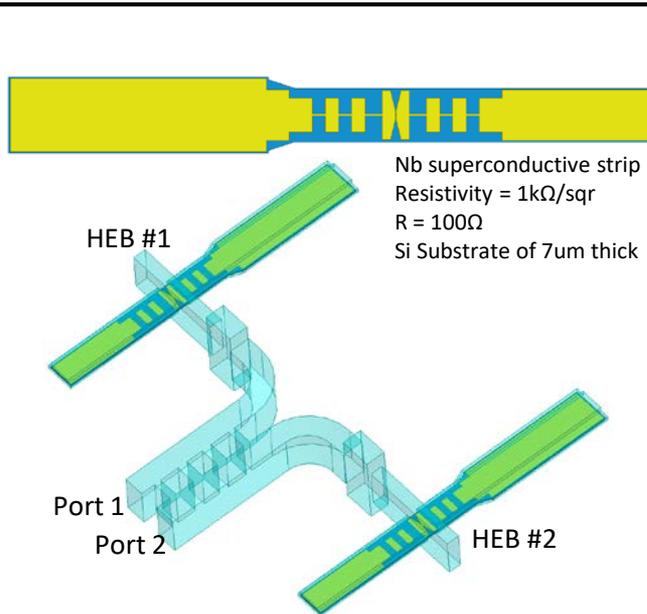
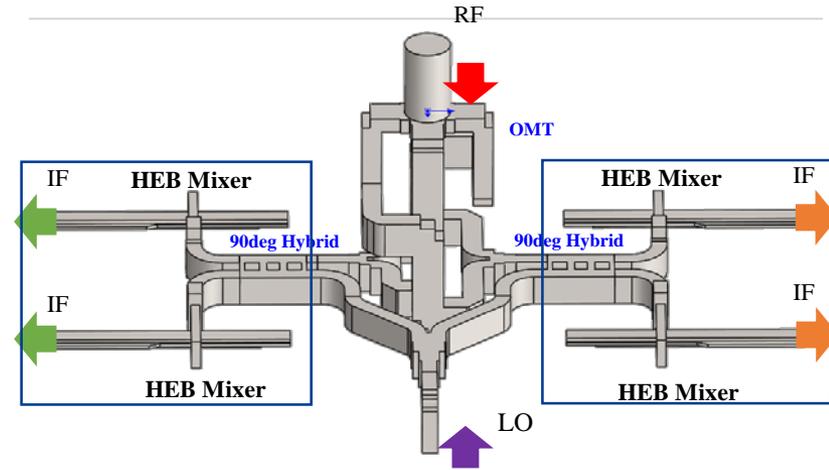
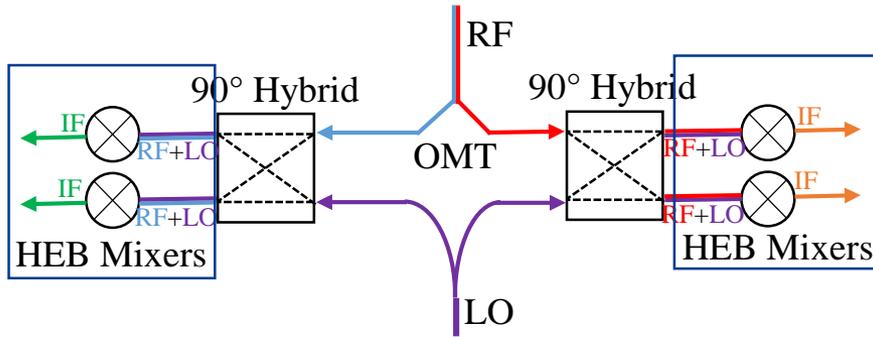
Ortho Mode Transducer at 1.9 THz



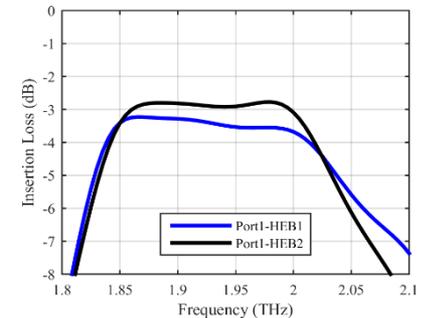
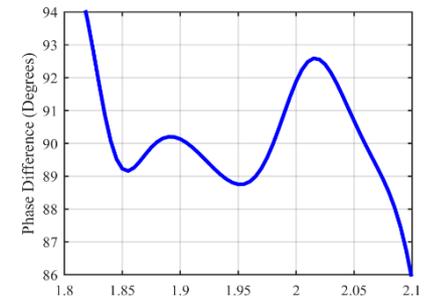
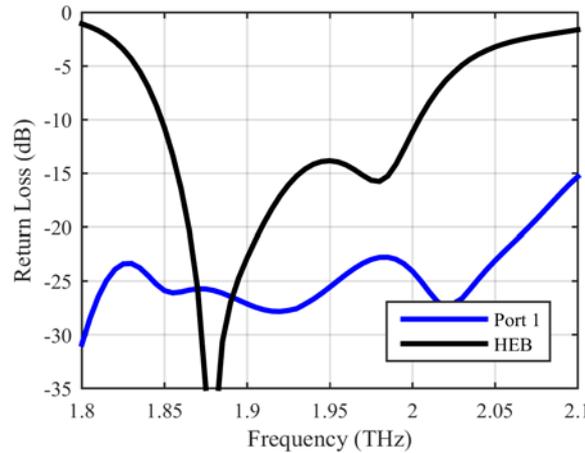
90-Degrees Hybrid Coupler at 1.9 THz



HEB Mixers at 1.9 THz

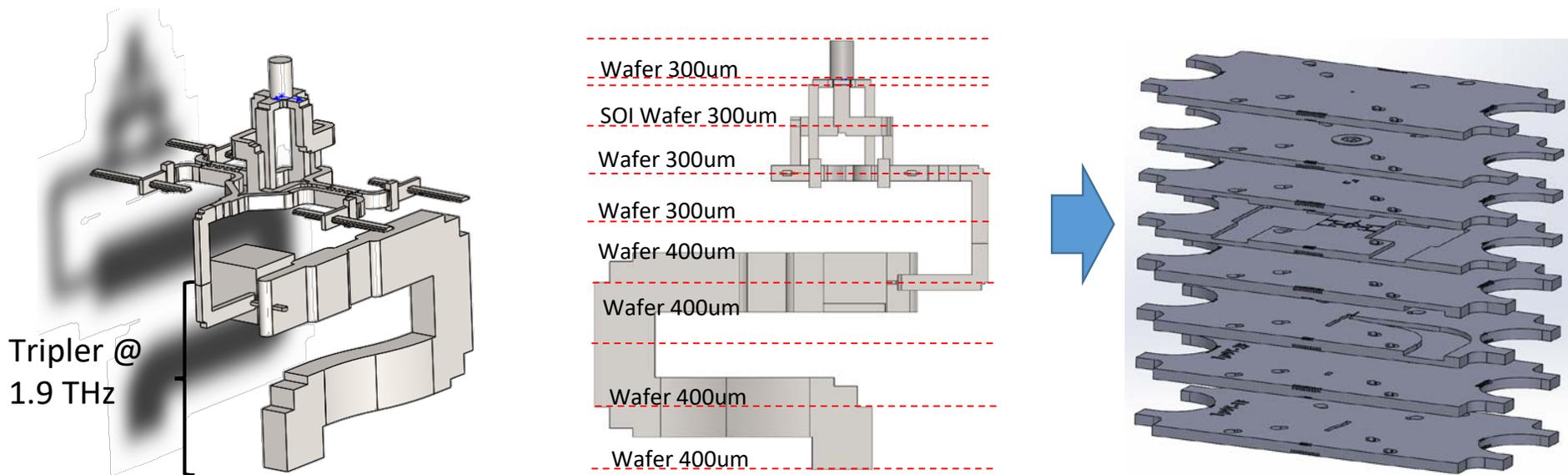


HEB Mixer



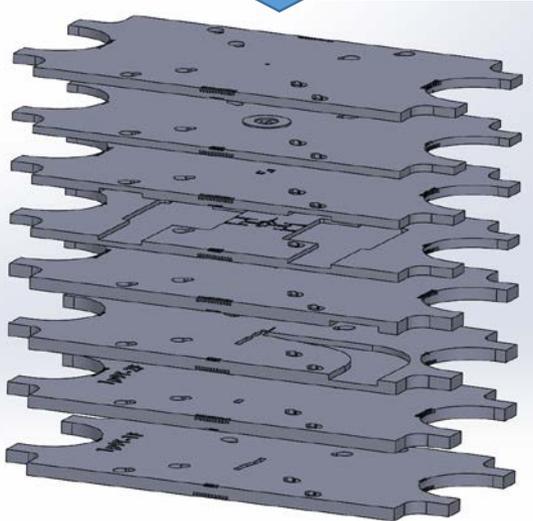
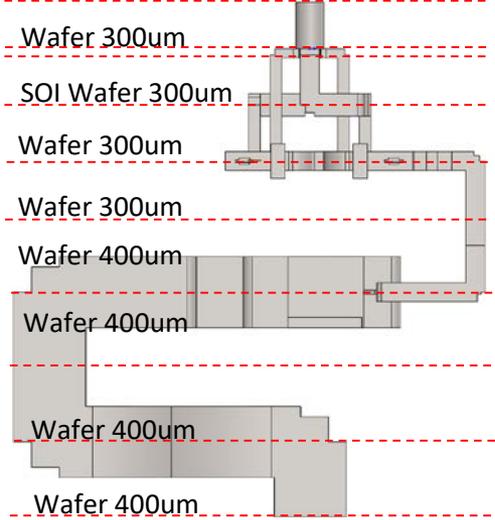
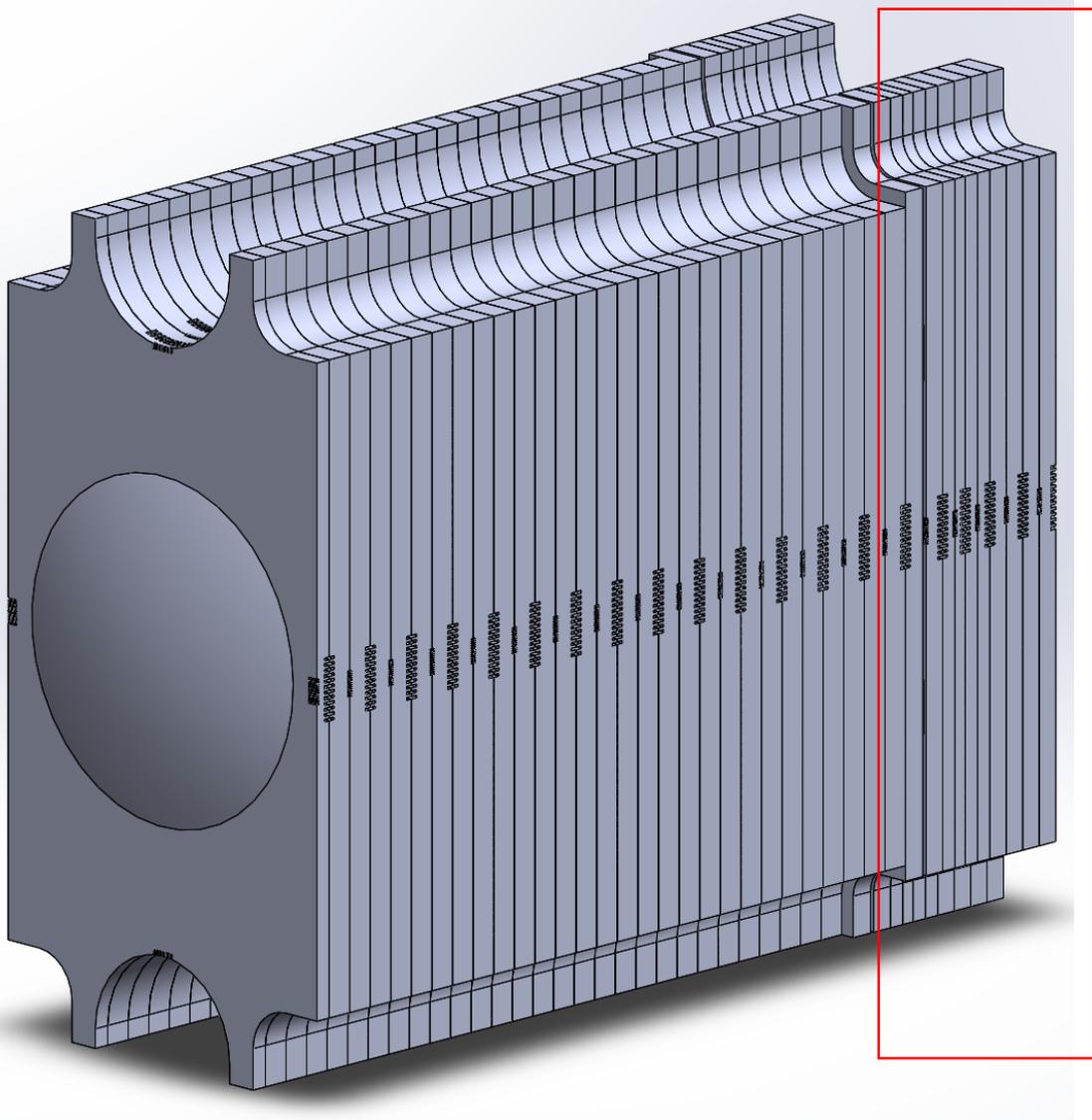
Receiver Integration

- Waveguide structures are fabricated on silicon wafers and coated with gold.
- They are vertically stacked

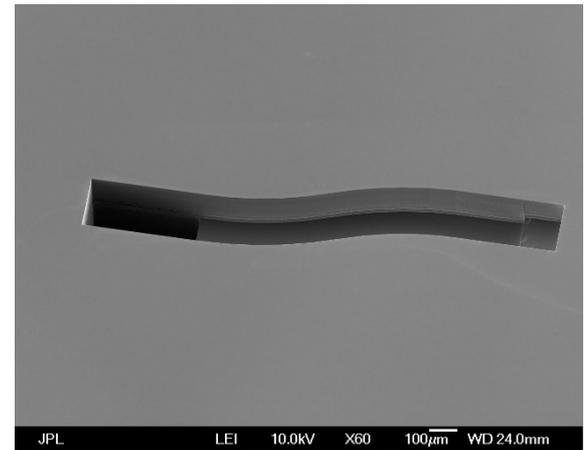
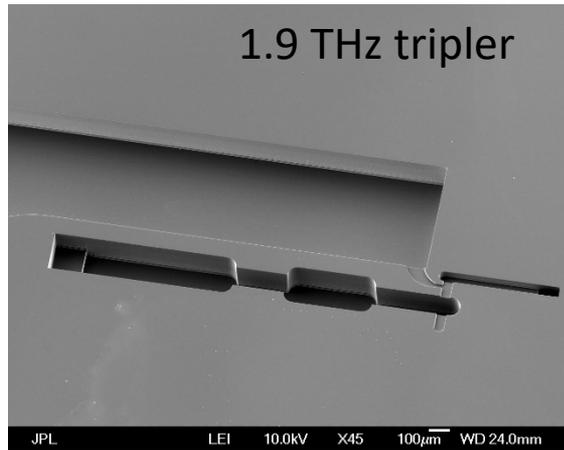
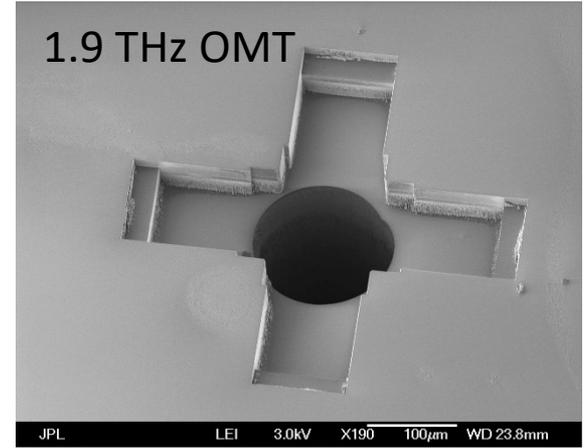
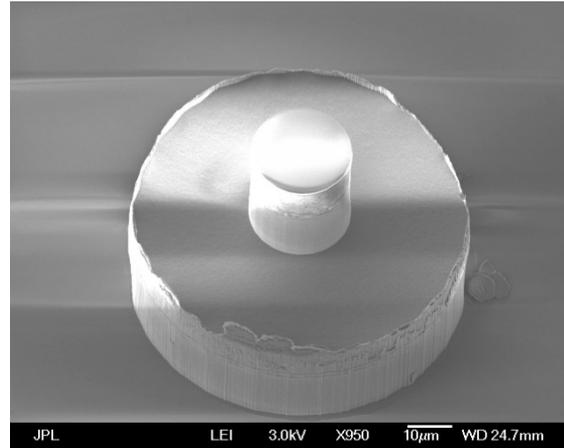
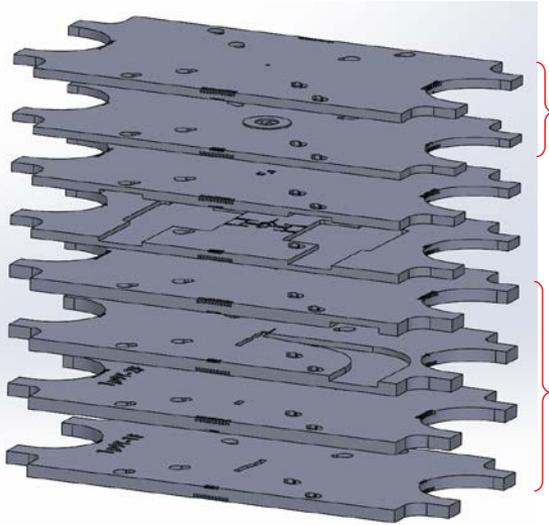


Ref: M. Alonso-delPino, T. Reck, C. Lee, C. Jung-Kubiak, N. Llombart, I. Mehdi, and G. Chattopadhyay, "Micro-Lens Antenna Integrated in a Silicon Micromachined Receiver at 1.9 THz," *Proc. 10th European Conference on Antennas and Propagation (EuCAP)*, Davos, Switzerland, April 2016.

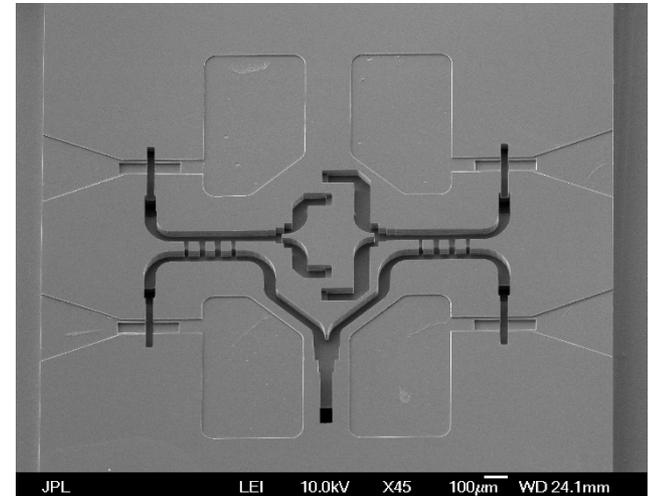
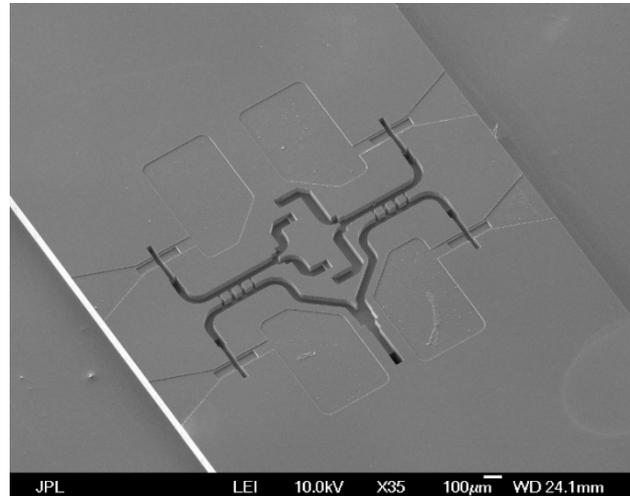
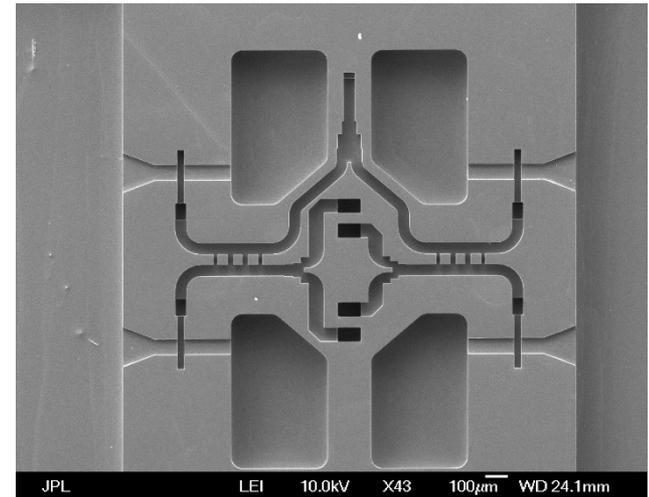
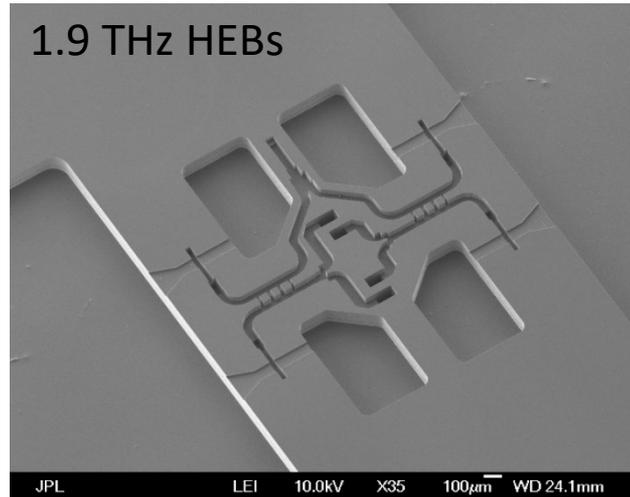
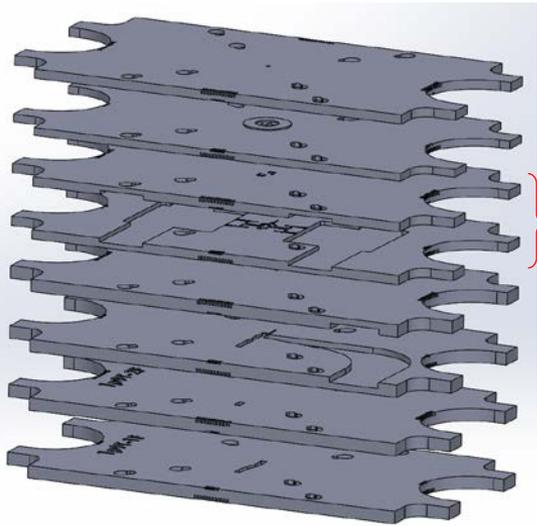
System Integration



Fabricated Components

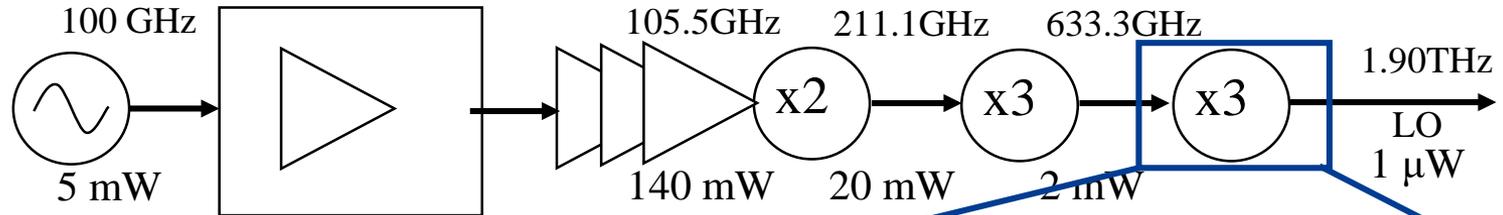


Fabricated Components

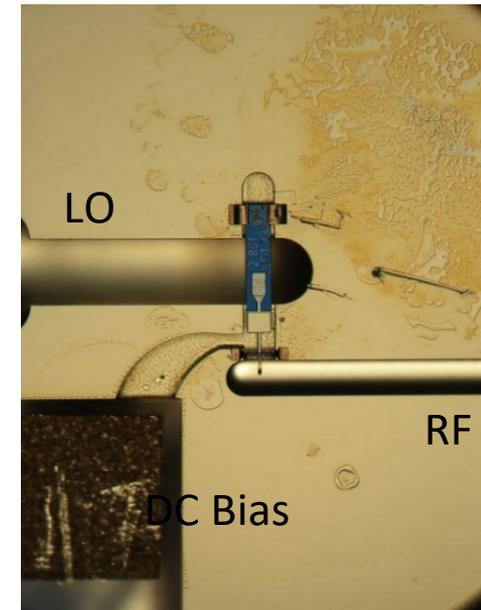
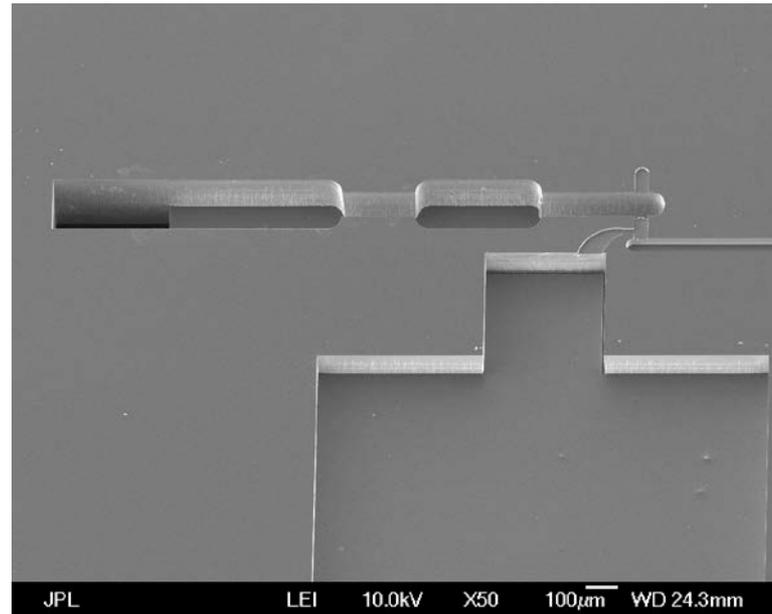
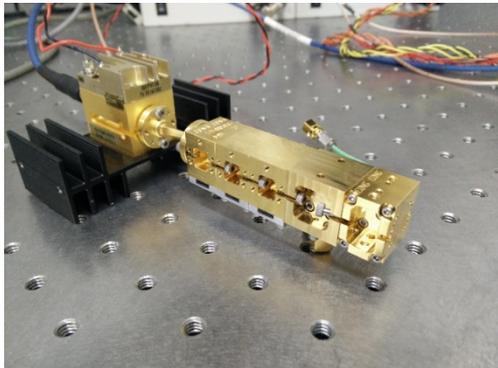


Ref: M. Alonso-delPino, T. Reck, C. Lee, C. Jung-Kubiak, N. Llombart, I. Mehdi, and G. Chattopadhyay, "Micro-Lens Antenna Integrated in a Silicon Micromachined Receiver at 1.9 THz," *Proc. 10th European Conference on Antennas and Propagation (EuCAP)*, Davos, Switzerland, April 2016.

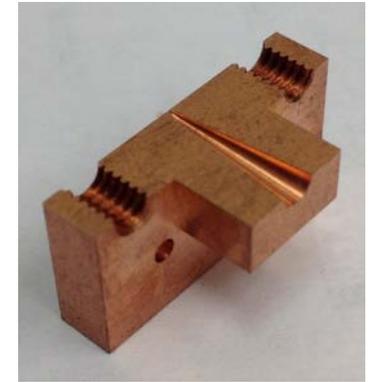
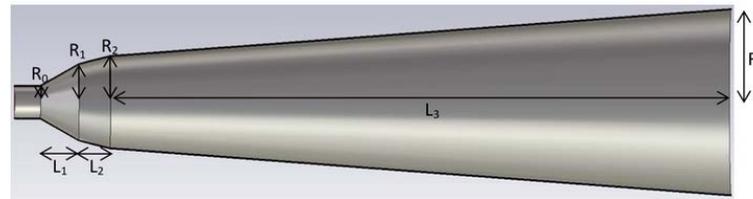
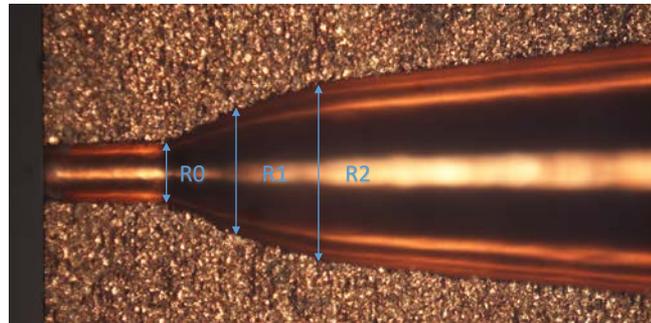
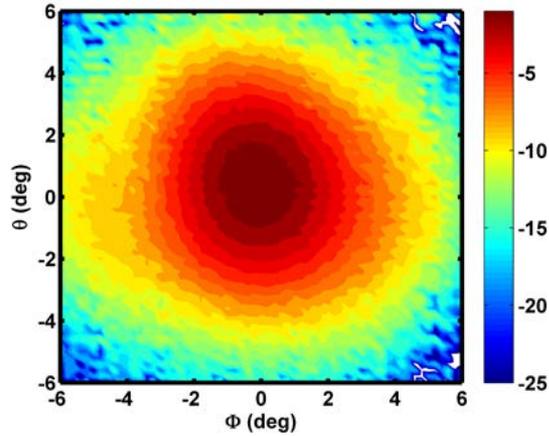
Local Oscillator Chain to Reach 1.9 THz



1.9 THz Tripler fabricated with Silicon Micromachining



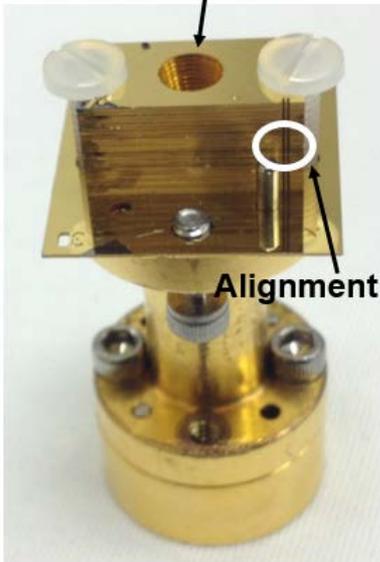
Terahertz Antennas



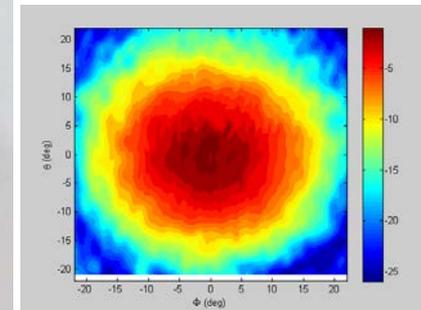
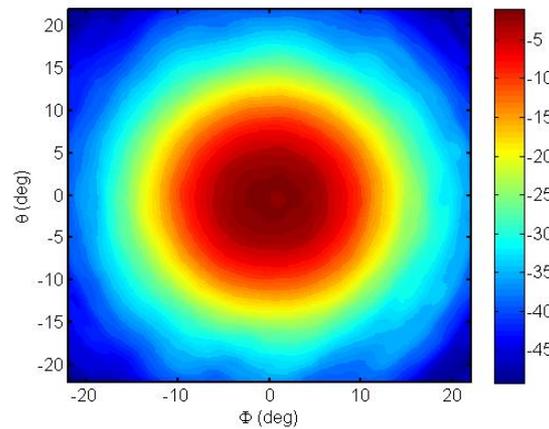
| Parameters | Length |
|------------|--------|
| R0 | 0.074 |
| R1 | 0.189 |
| R2 | 0.261 |
| R3 | 1.279 |
| L1 | 0.237 |
| L2 | 0.237 |
| L3 | 8.976 |

Total length = 9.45mm.

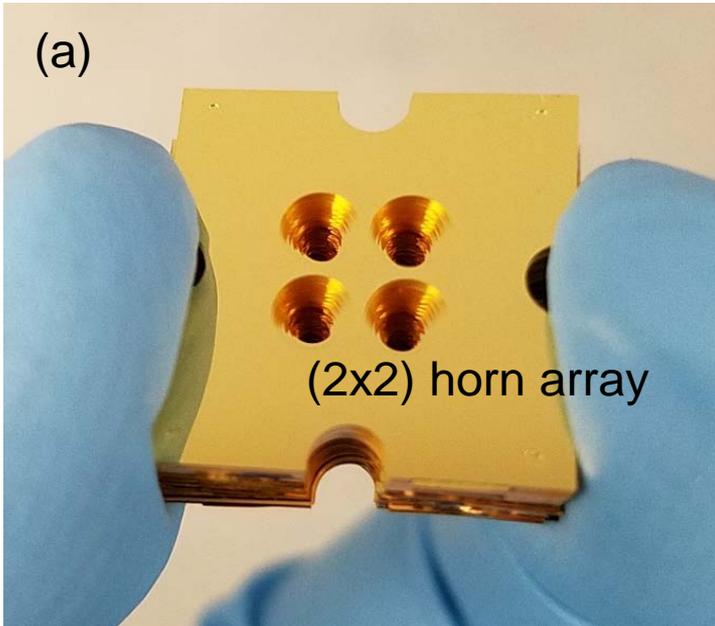
Horn Aperature



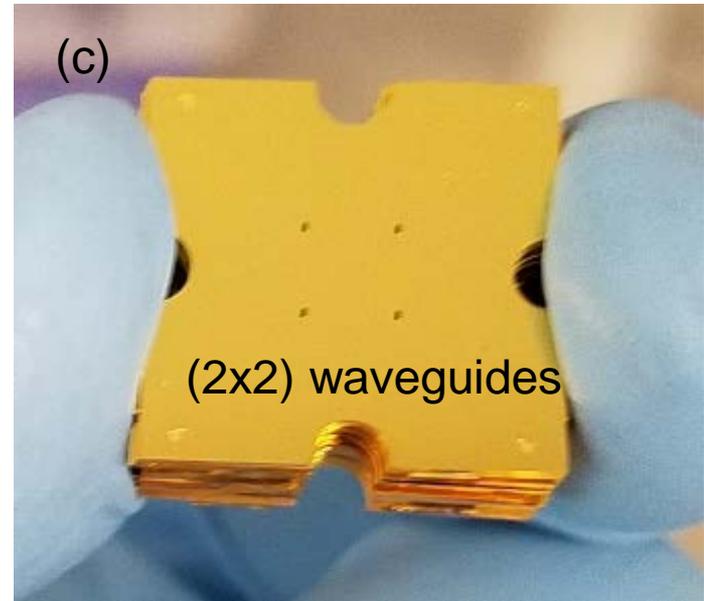
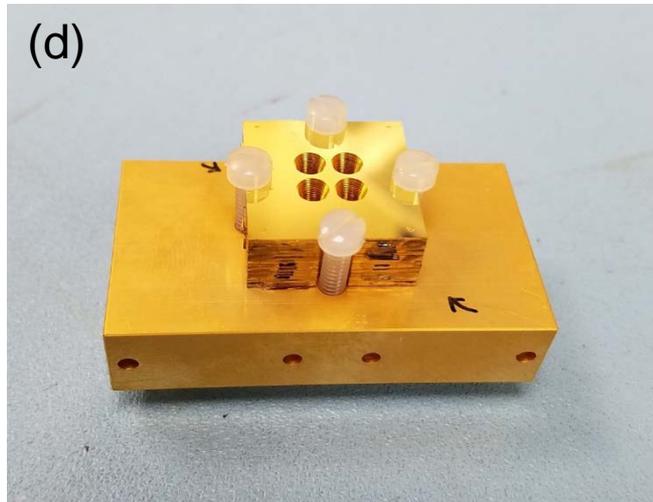
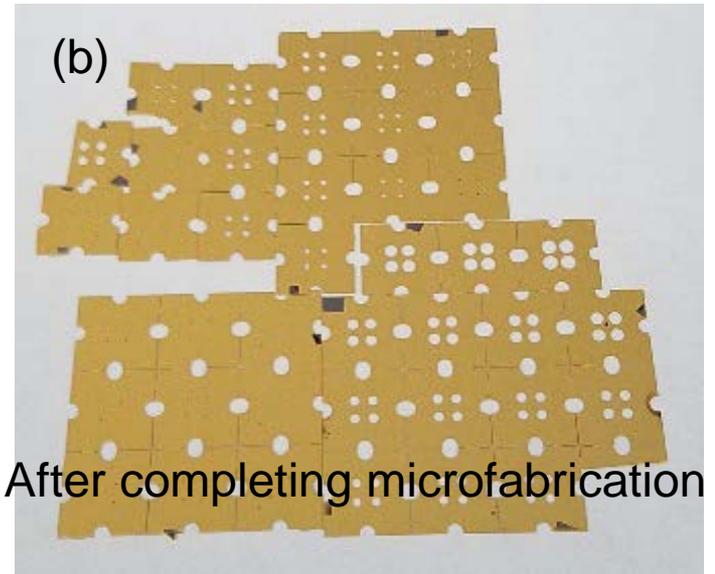
Alignment check



Terahertz Antennas



38 silicon layers stacked



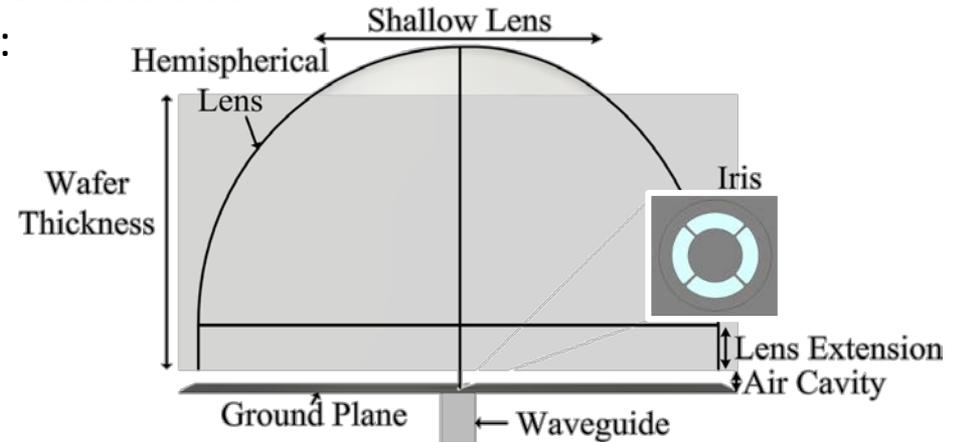
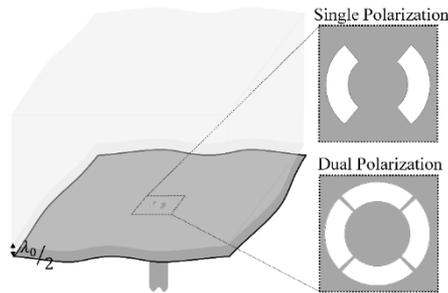
Silicon Microlens Antenna

- **High Aperture Efficiency, Gaussicity and Low Cross-Pol**

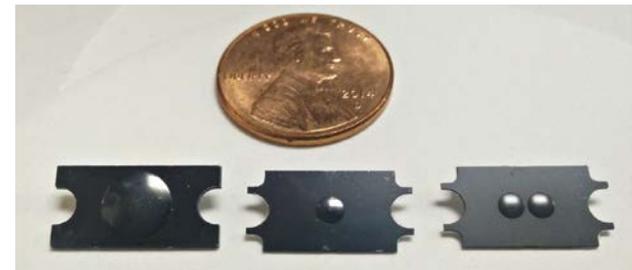
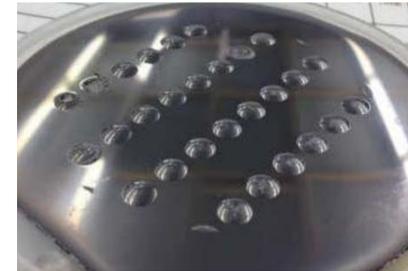
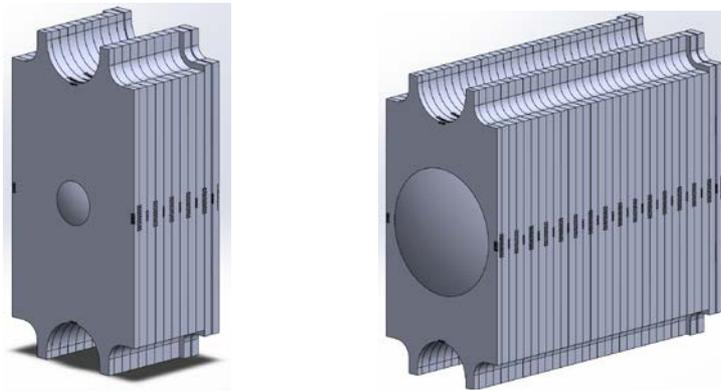
Very directive waveguide feed which improves:

- Phase Loss
- Reflections

- **Dual-Polarized**



- **Compatible with silicon micro-machining techniques**
- **Allow wafer level integration for array manufacturing**



Ref: N. Llombart *et al.*, "Silicon Micromachined Lens Antenna for THz Integrated Heterodyne Arrays," in *IEEE Transactions on Terahertz Science and Technology*, vol. 3, no. 5, pp. 515-523, Sept. 2013.

Silicon Microlens Fabrication

(1) Photoresist patterning



(2) Thermal reflow



(3) Selective Etching

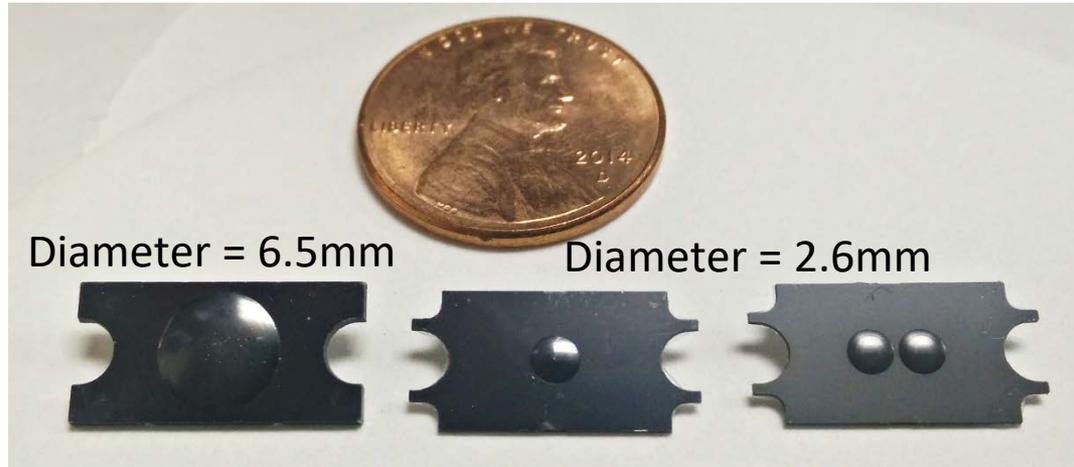


(4) Complete etching



■ Silicon

■ Photoresist

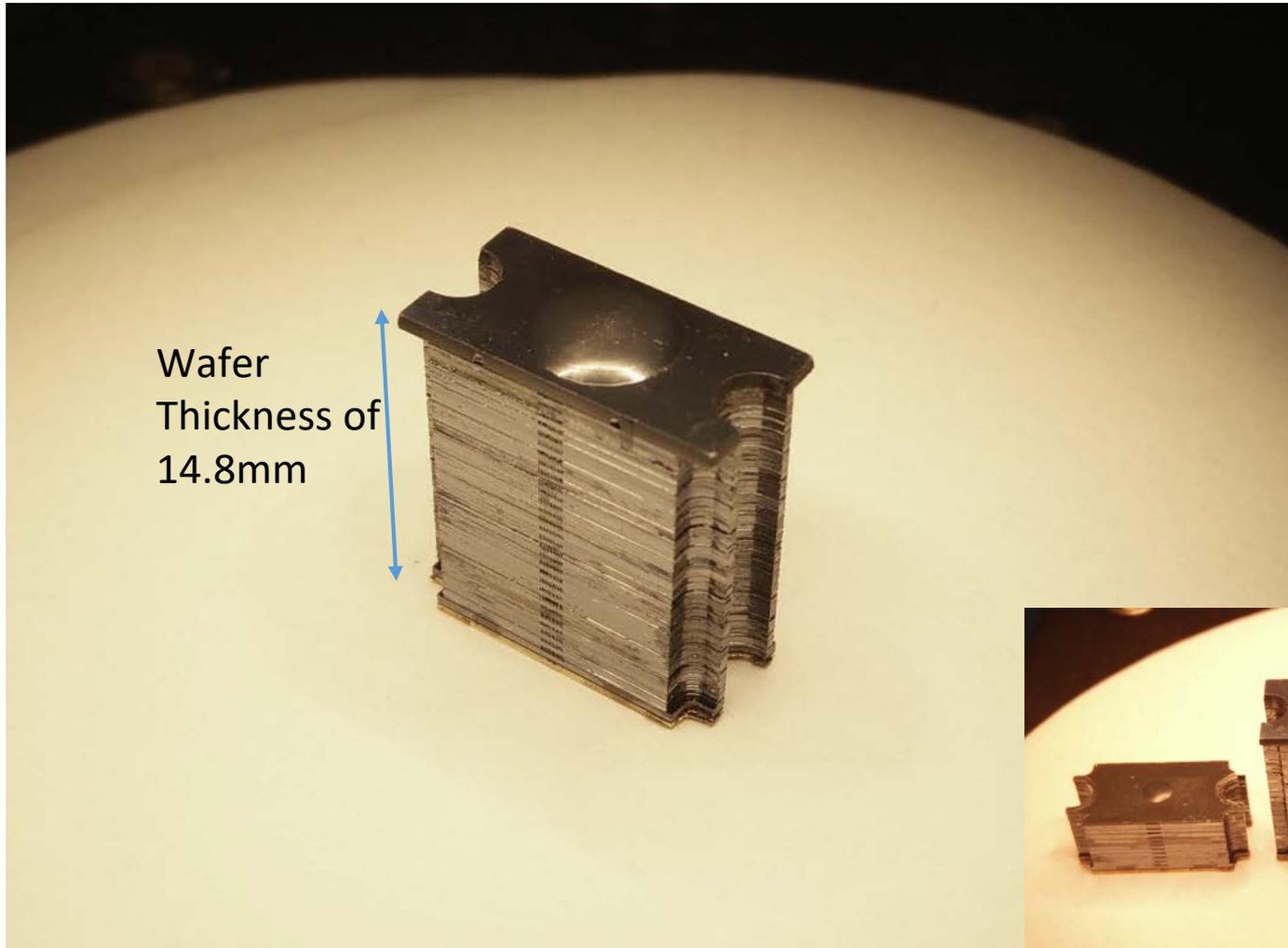


Diameter = 6.5mm

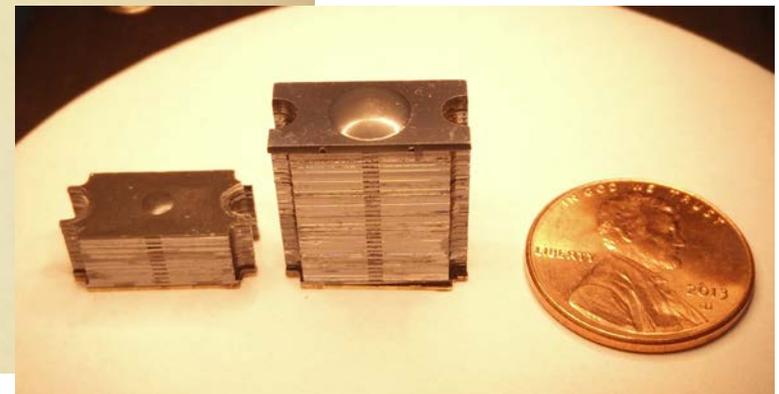
Diameter = 2.6mm

Deposition of 30 μ m of Parylene-C coating as matching layer ($n = 1.62$)

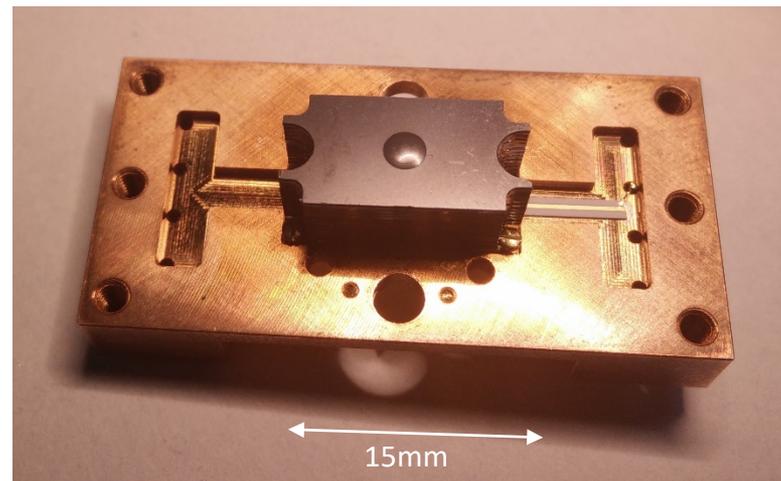
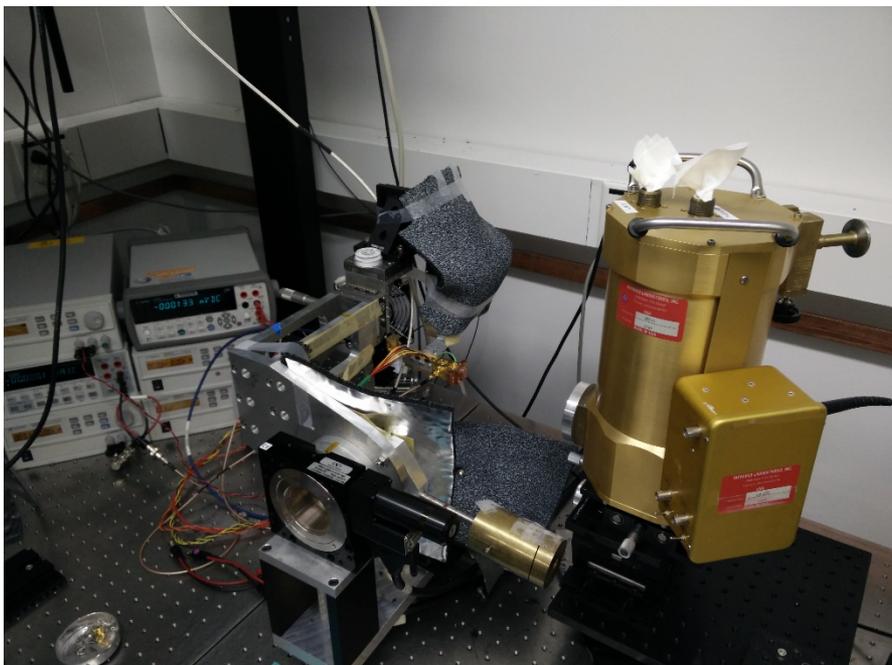
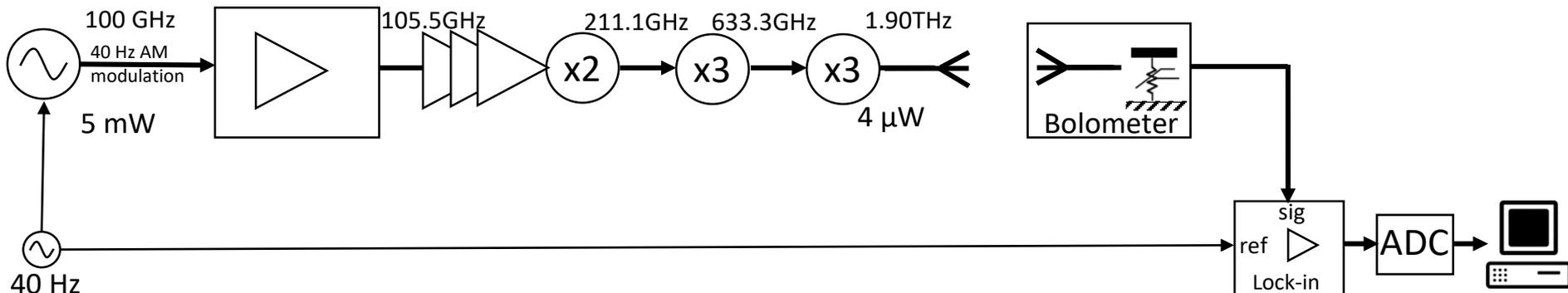
Silicon Microlens Assembly



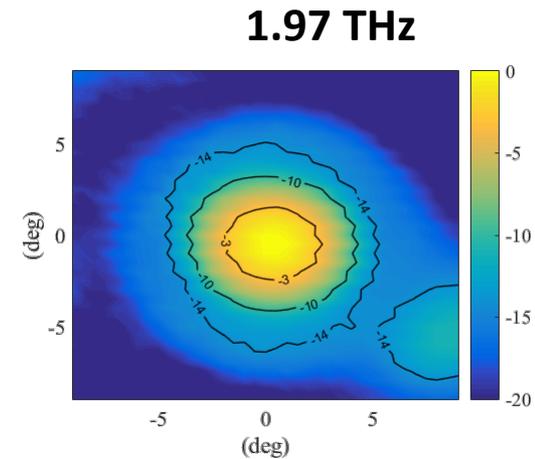
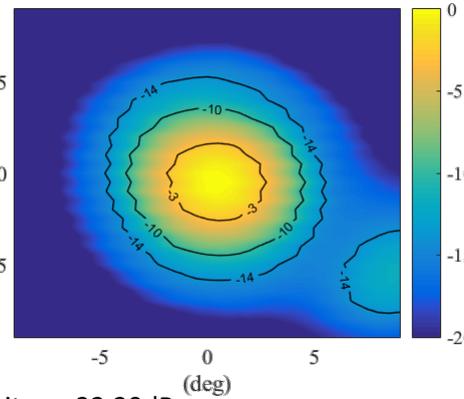
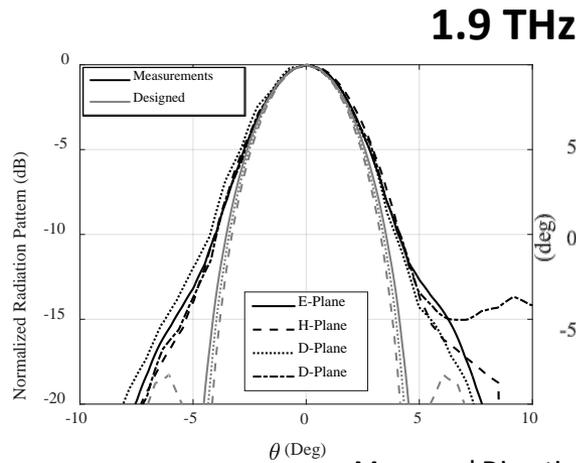
29 Wafers Assembled!
(Including Lens, Iris and Posts)



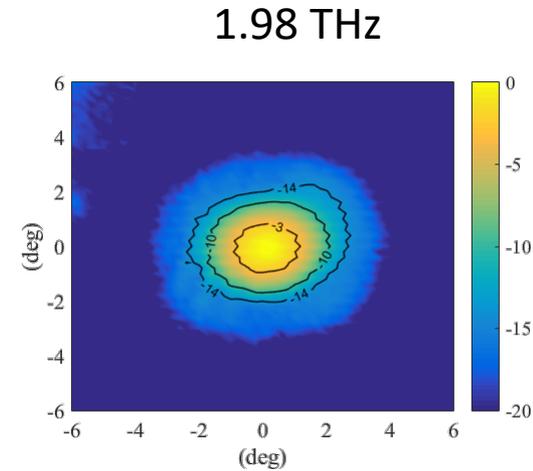
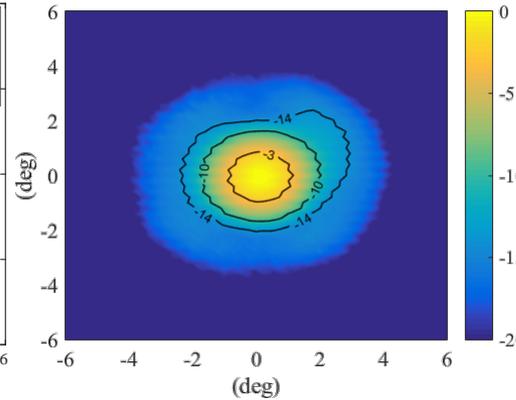
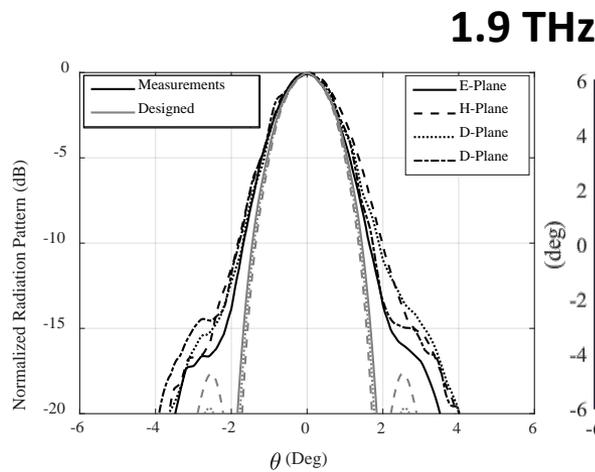
Antenna Measurement Setup at 1.9 THz



Measured Radiation Pattern



Measured Directivity = 32.29dB
Designed Directivity = 33.83dB



Measured Directivity = 39.21dB
Designed Directivity = 41.66dB

Ref: M. Alonso-delPino, T. Reck, C. Jung-Kubiak, C. Lee, and G. Chattopadhyay, "Development of Silicon Micromachined Microlens Antennas at 1.9 THz," *IEEE Transactions on Terahertz Science and Technology*, vol. 7, no. 2, pp. 191-198, March 2017.

Antenna Performance Comparison

| | Lens 2.5mm | Lens 6.2mm | Horn 2.5mm |
|--------------------------------|---------------|---------------|---------------|
| Illuminated Aperture | 2.539mm | 6.128mm | 2.524mm |
| Gaussicity (%) (-10dB) | 85.65% | 84.87% | 83.32% |
| Directivity | 32.29dB | 39.21dB | 30.93dB |
| Illumination Efficiency | 66.39% | 56.13% | 47.82% |

Illumination Efficiency:

It expresses the uniformity of the field distribution on the aperture of the antenna $\eta_{il} = \frac{\lambda^2 Directivity}{4\pi Area}$

